

Joining II

Processes and Types



Importance of Assembly and Joining

Why focus on Assembly?



parts: 1



4

Approximate Number of Parts in Products

Common pencil	4
Rotary lawn mower	300
Grand piano	12,000
Automobile	15,000
Boeing 747-400	6,000,000

Assemblies actually do things customers want

Get it Right the First Time...

TABLE I.5

Stage	Relative cost of repair
When the part is being made	1
Subassembly of the product	10
Assembly of the product	100
Product at the dealership	1000
Product at the customer	10,000

“The Multiplier” According to Ford and GM or: Why Is DFM/DFA Important?

- For every product part, there are about 1000 manufacturing equipment parts*
- Or, for every toleranced dimension or feature on a product part, there are about 1000 toleranced dimensions or features on manufacturing equipment
- Such “equipment” includes fixtures, transporters, dies, clamps, robots, machine tool elements, etc

*Note: Ford’s estimate is 1000, GM’s is 1800. Both are informal estimates.

Joining I

Manufacturing Assemblies

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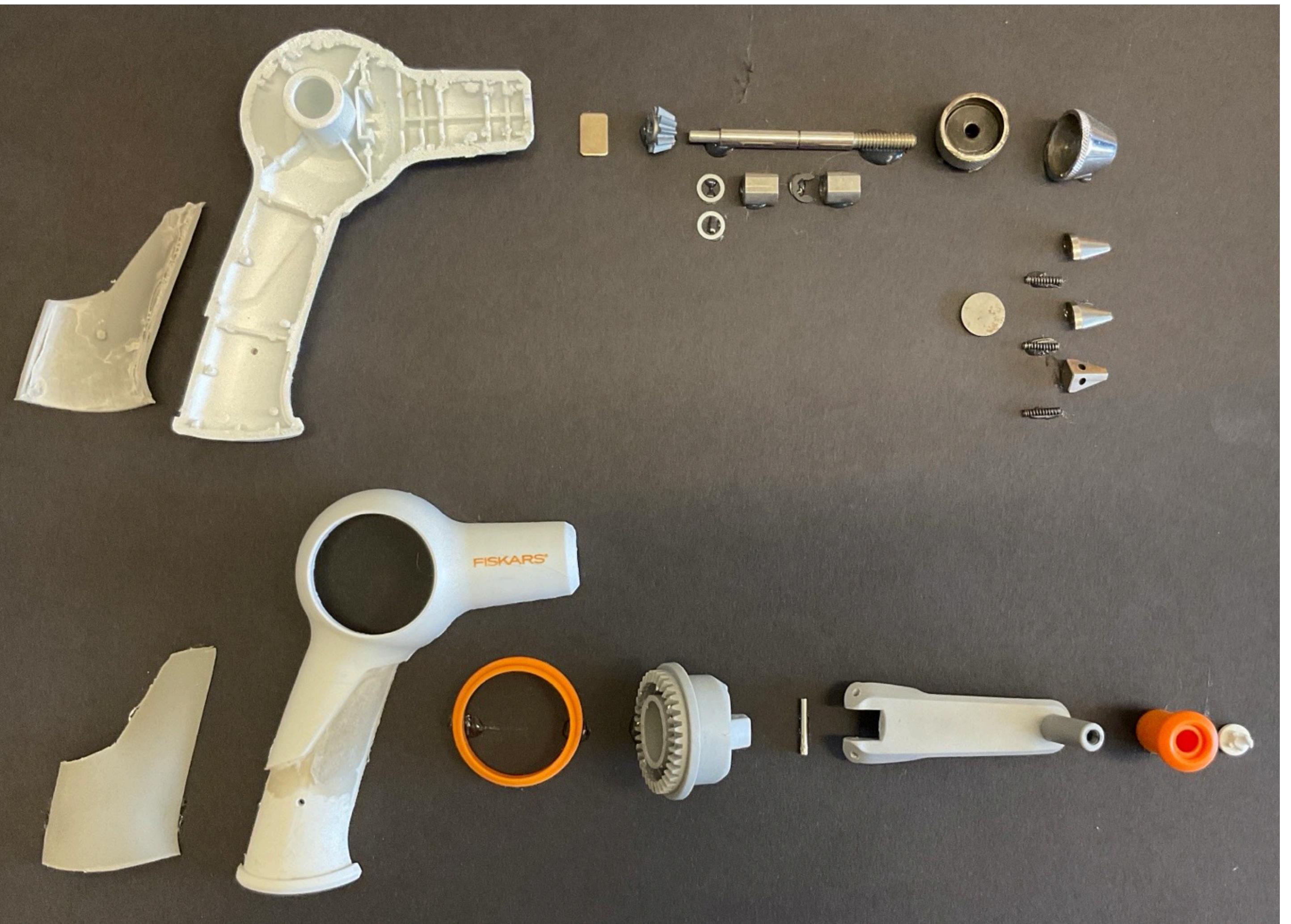
DFA: Design for Assembly

1. Reduce the Part Count

- relative motion
- material properties
- otherwise impossible
- maybe disassembly: for recycling

2. Make Each Part Easier to Assemble

Note: parts still need to be
manufacturable (DFM still applies: DFMA)

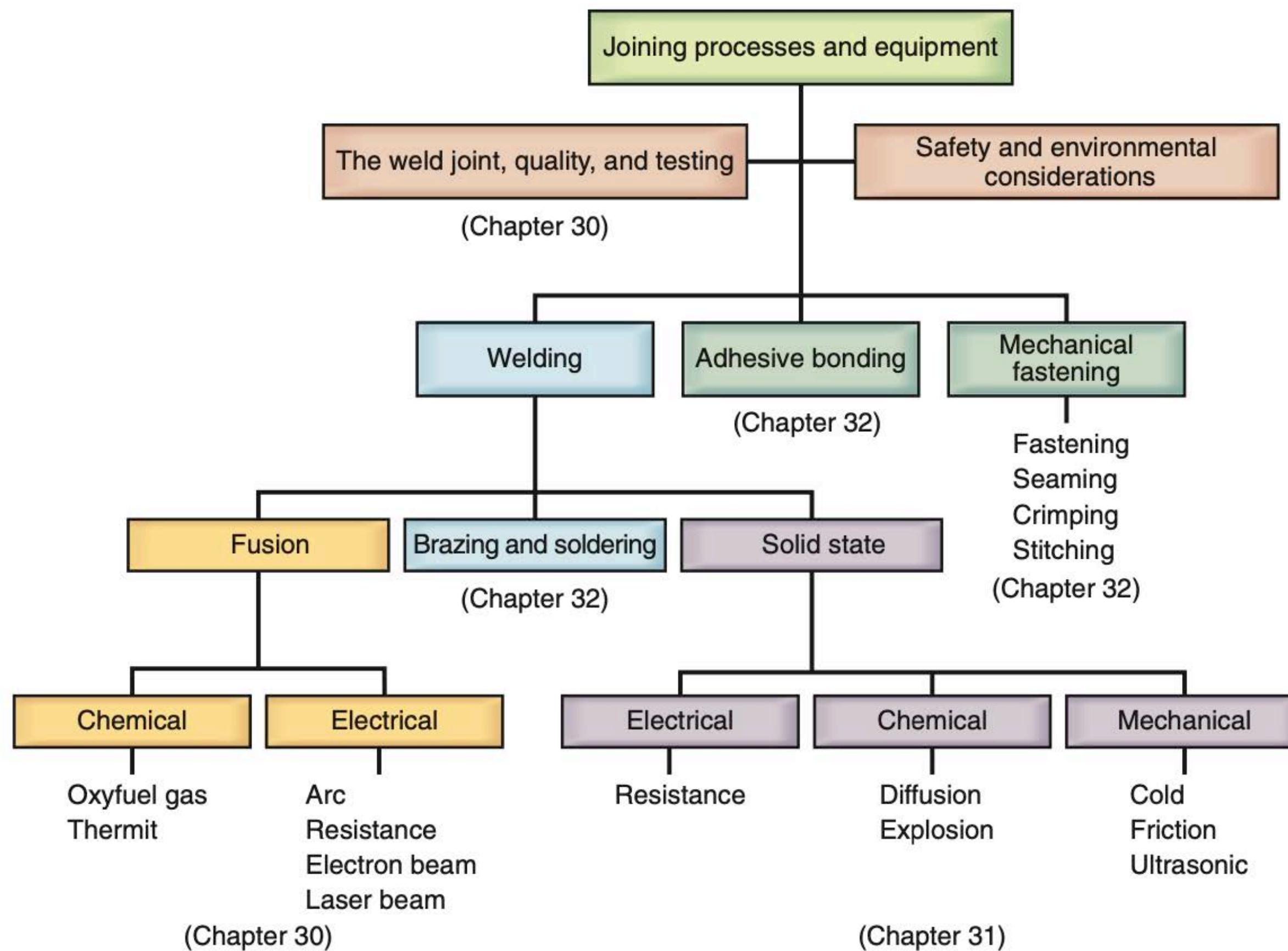


Joining I

Manufacturing Assemblies

Process Planning: Your “Well Orchestrated Dance” Plan

which manufacturing methods + joining methods (plus all of the logistical details to make it happen)



Selection Criteria

- geometry (sheet example)
- material type
- size of production run
- **value of end product**

car: \$40k for 4,000lbs: ~\$10/lb

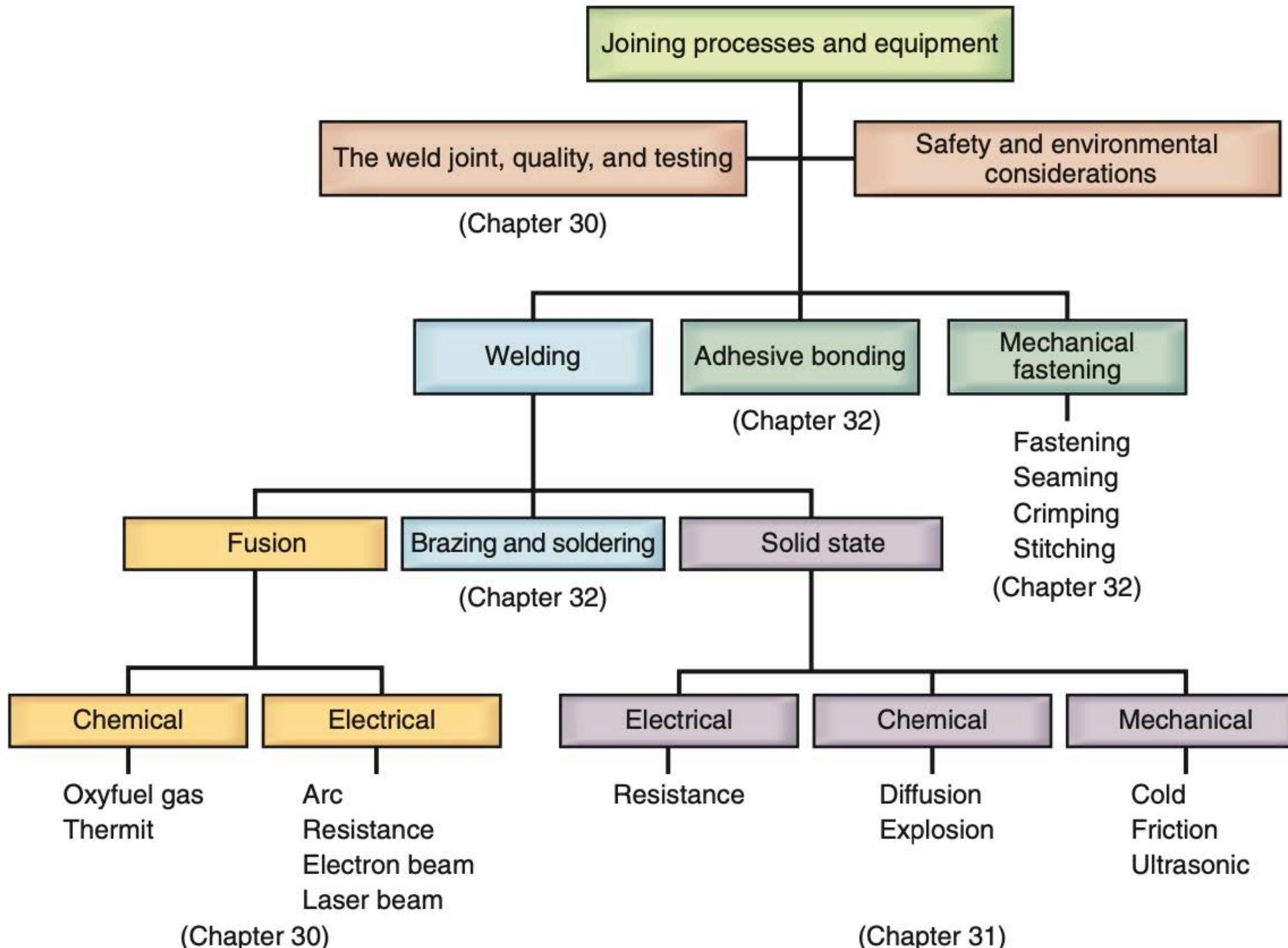
airplane: \$1,000/lb (sensitive to weight increase)

satellite: \$10,000/lb

Joining II

Processes and Types

Joining Processes



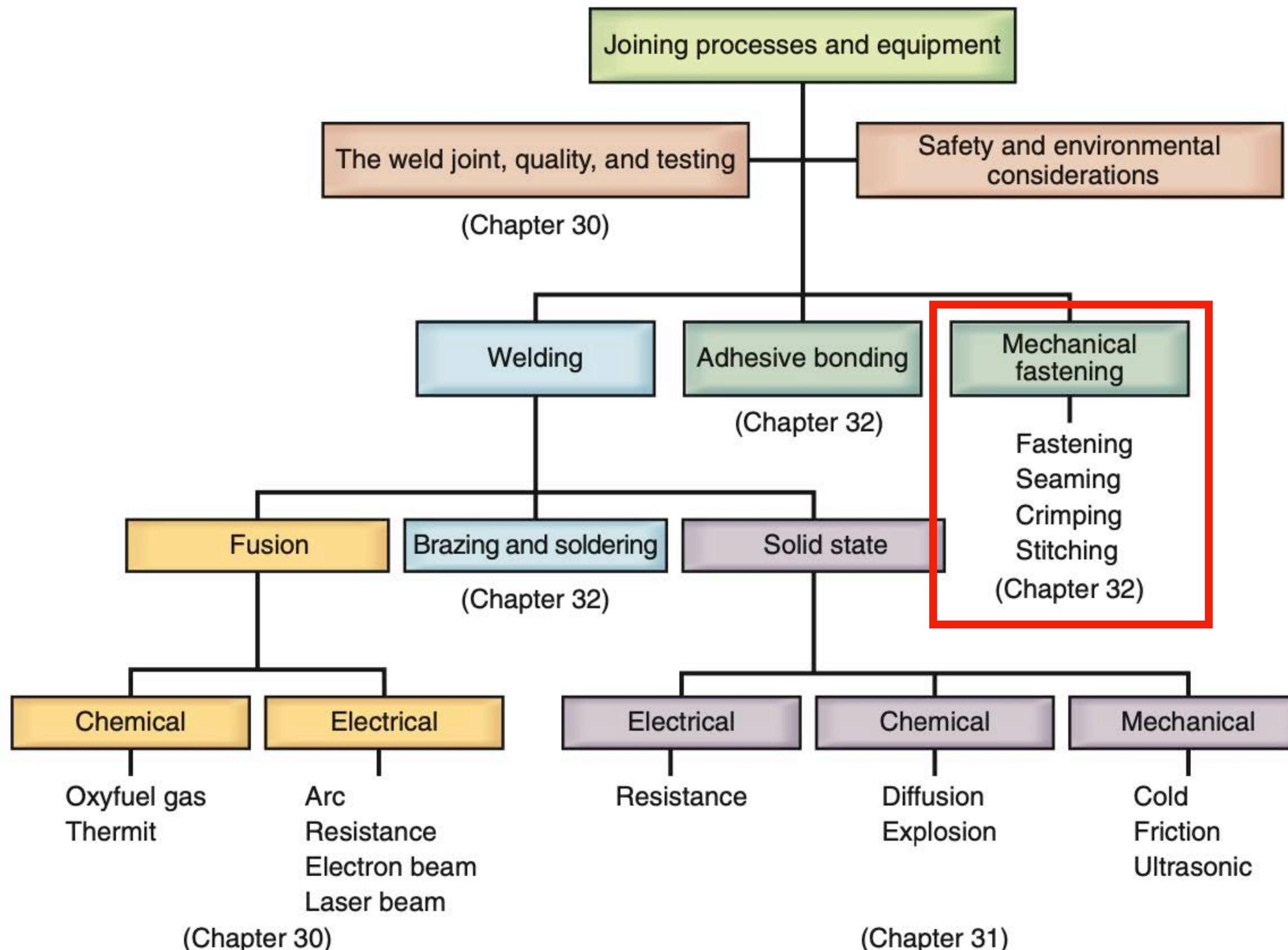
Design for Joining

- design parts with that joining method in mind
- ease of locating/aligning (self-location, self-alignment)

Joining II

Processes and Types

Joining Processes



Mechanical Fastening

Joining II

Processes and Types

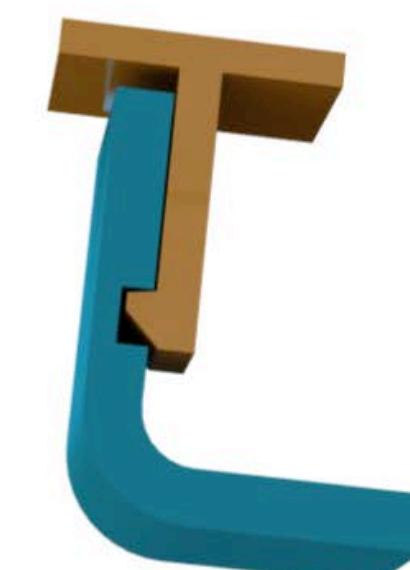
8

Mechanical Fastening



Type of Fasteners

- bolts/screws
 - disassembly/reassembly
 - cross threading
- rivets
 - when disassembly not required
- dowel pins
- cotter pins
- snap fits



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Mechanical Fastening



Considerations

- any shape and material
- semi-permanent
- least expensive for low volume
- limited strength and sealing
- increases part count
- assembly can be challenging
- loosen over time

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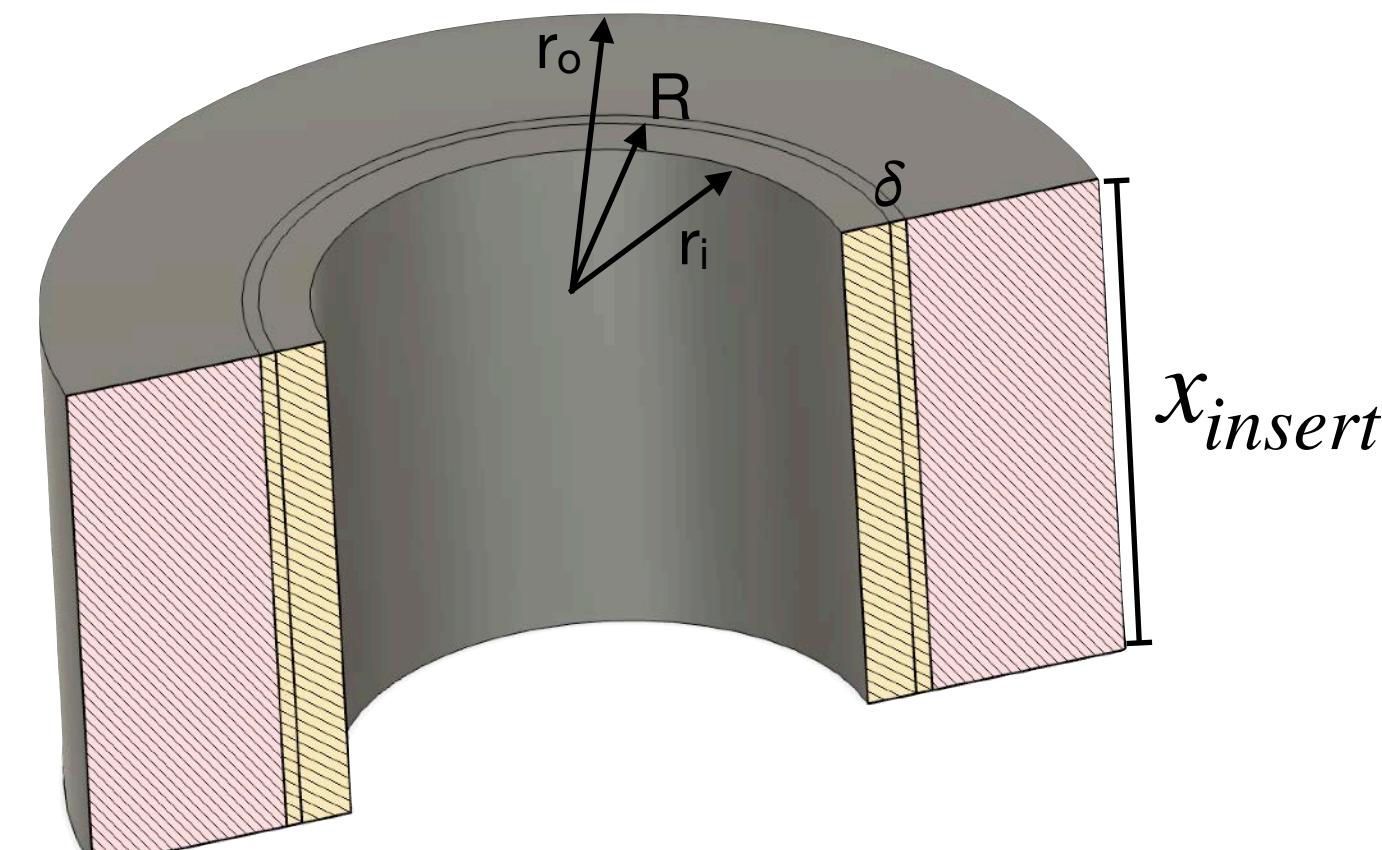
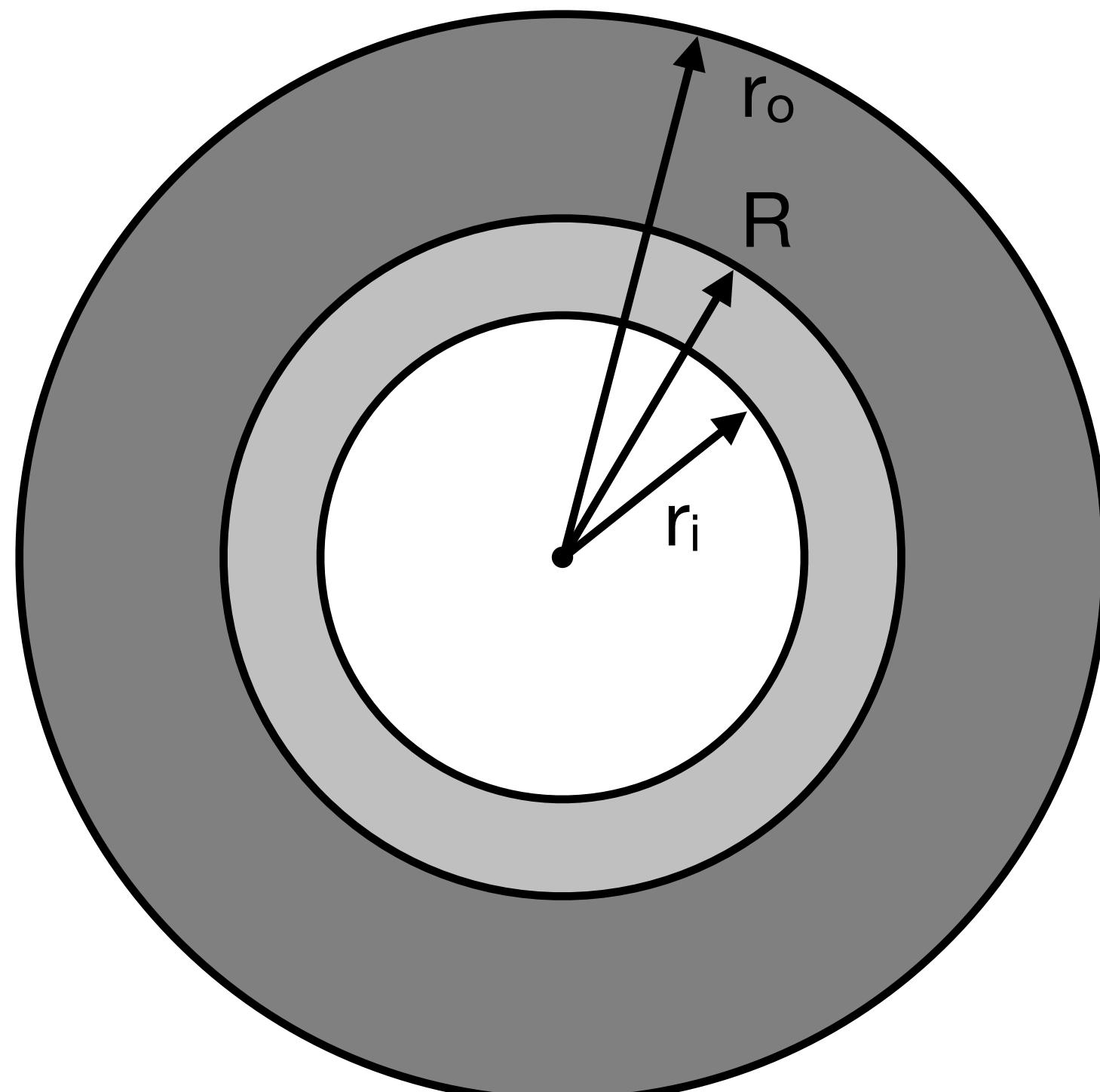
Processes and Types

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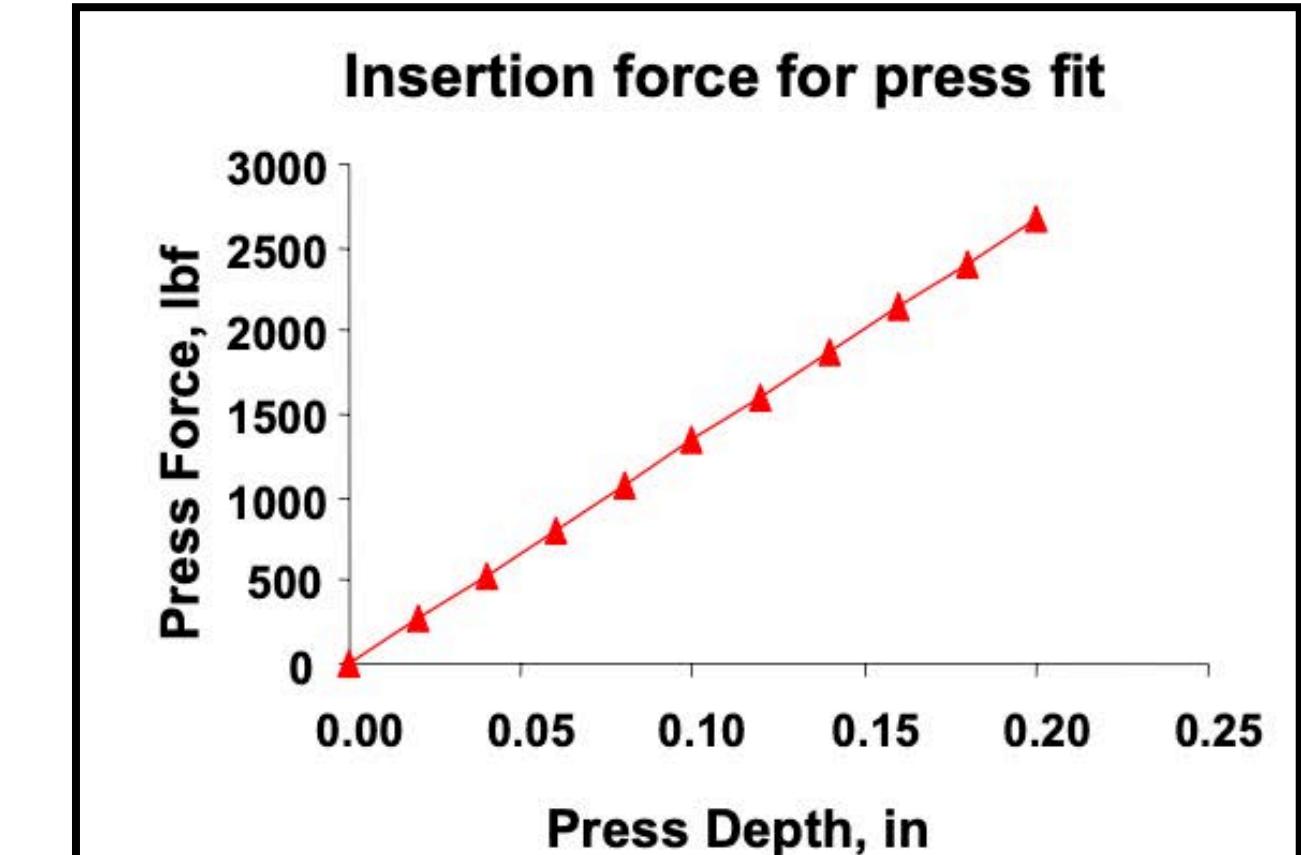
Mechanical Fastening: Press/Shrink Fits

two cylinders of the same length pressed to interfere

or, one body is **heated** to expand, and then allowed to **cool** over the other part



$$p = \frac{E}{R} \delta \left(\frac{(r_0^2 - R^2)(R^2 - r_i^2)}{2R^2(r_0^2 - r_i^2)} \right) \rightarrow F_{insert} = \mu p 2\pi R x_{insert}$$



$$\delta_{thermal} = \alpha R \Delta T$$

p: interface pressure, [Pa] or [psi]

E: Young's Modulus, [Pa] or [psi]

δ : radial interference [m] or [in]

α : coefficient of thermal expansion [deg $^{-1}$] !

ΔT : temperature change [deg]

x_{insert} : length of engagement [m] or [in]

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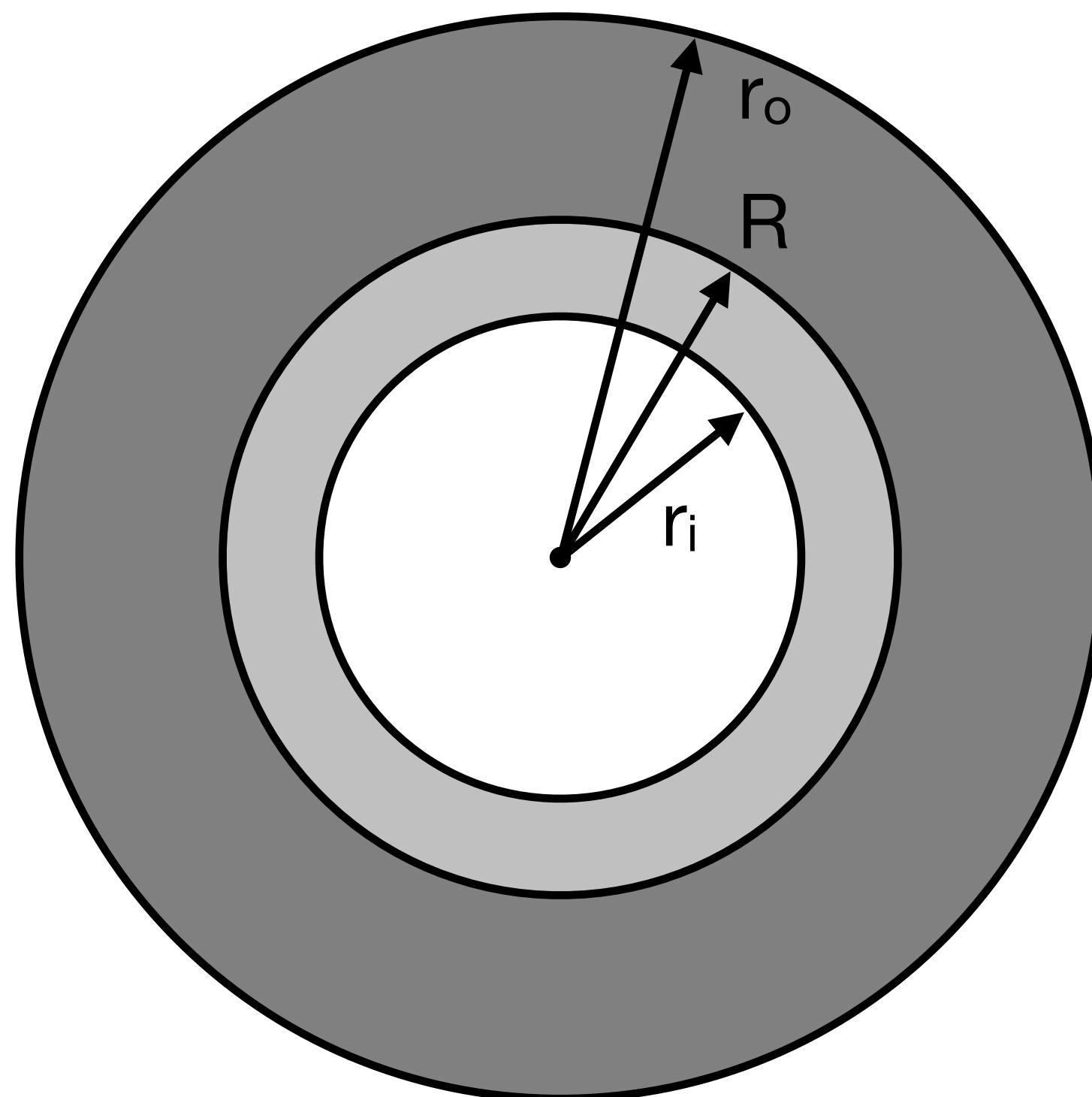
Processes and Types

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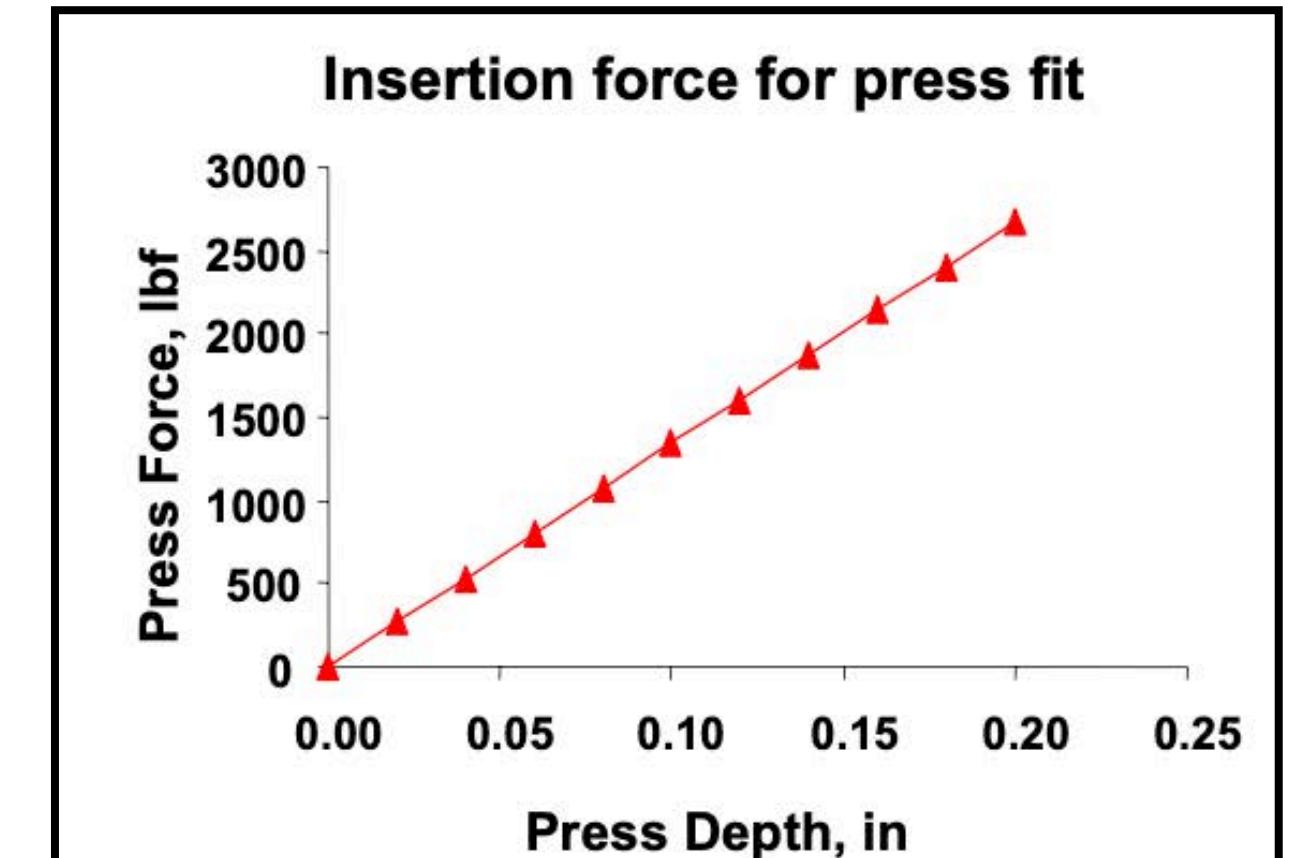
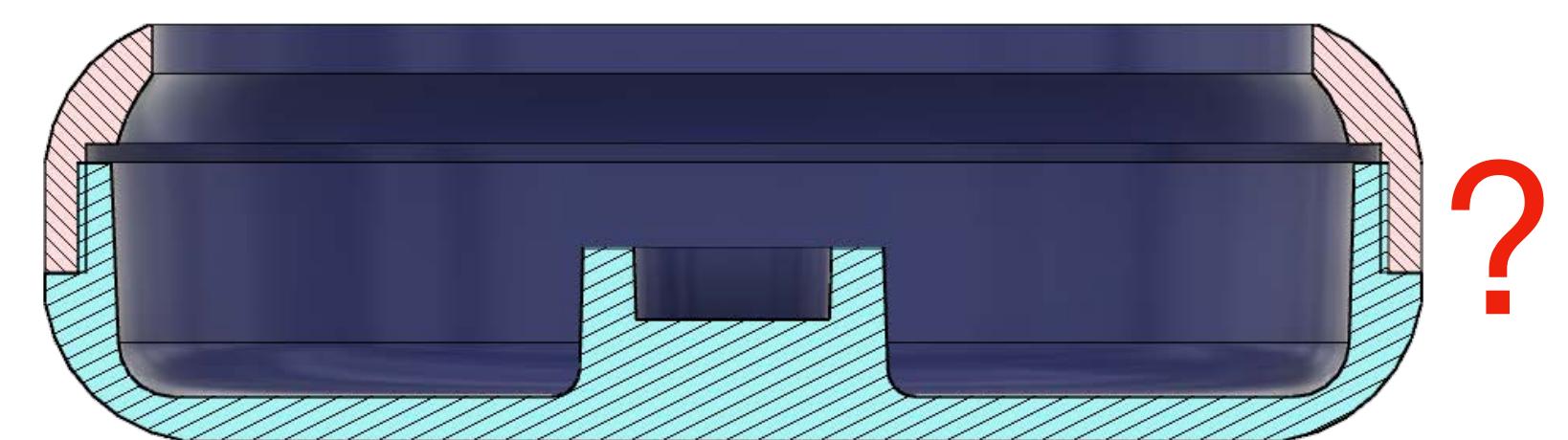
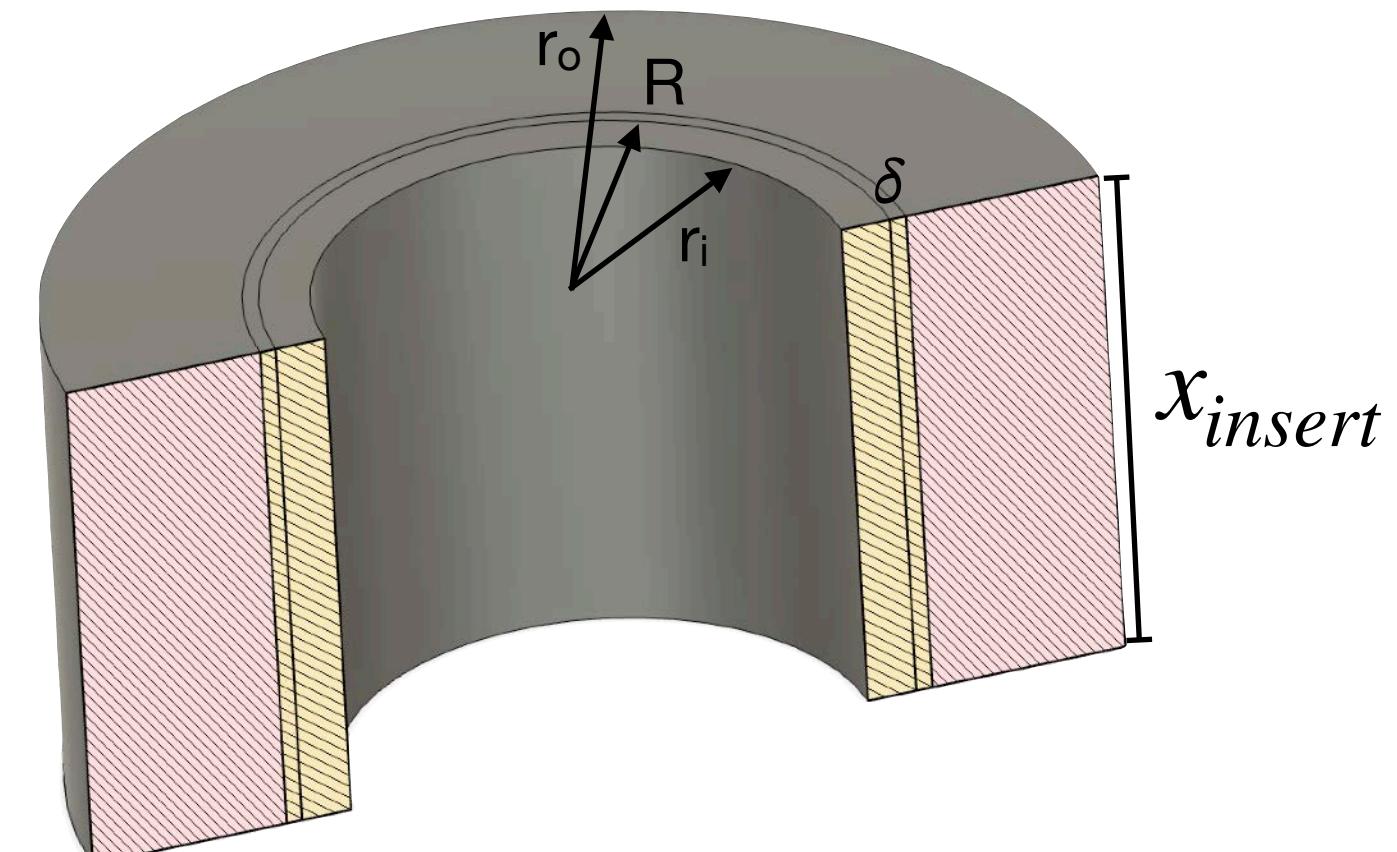
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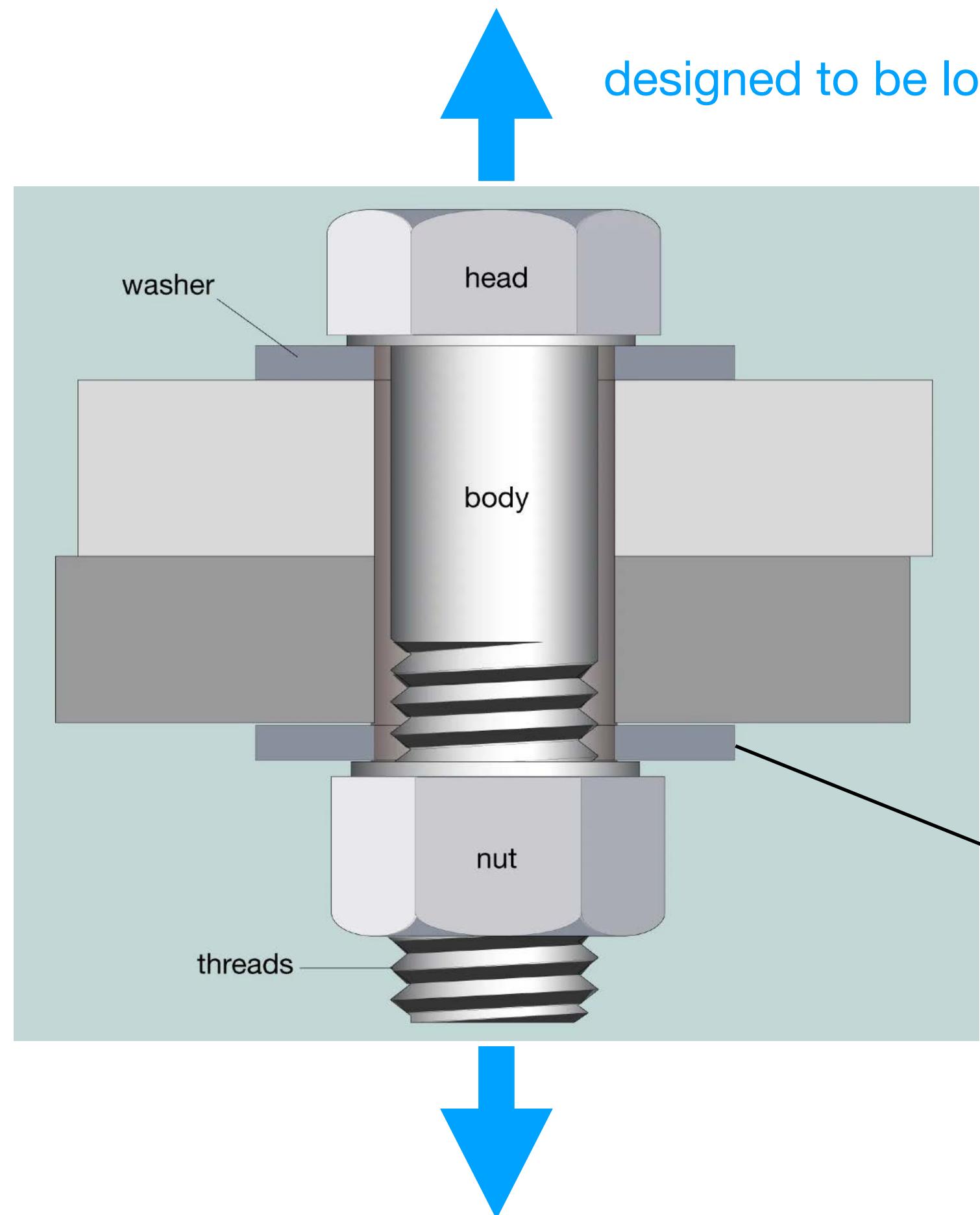


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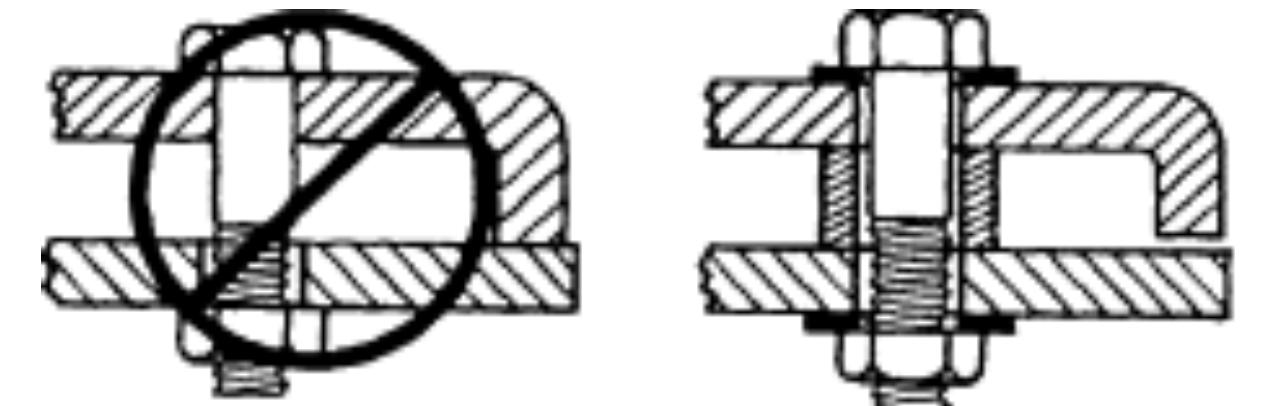
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DF: Mechanical Joining

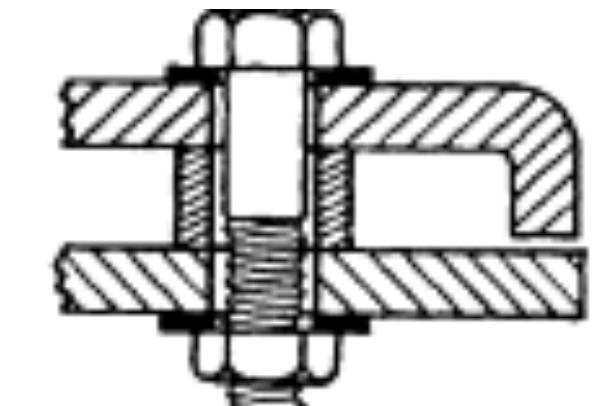


washers: distribute load (can provide locking/preload)

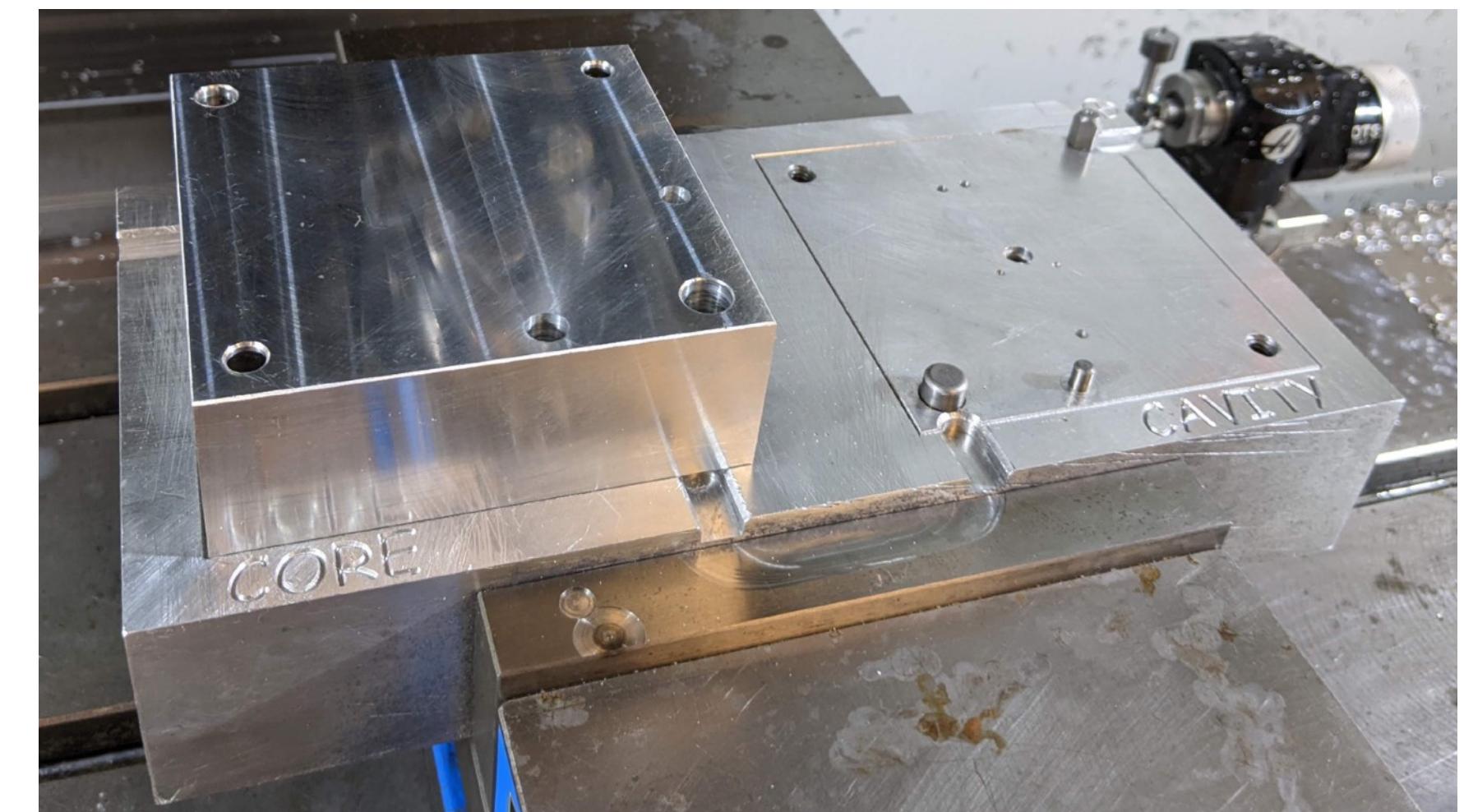
consider how the material is loaded



Incorrect



Correct

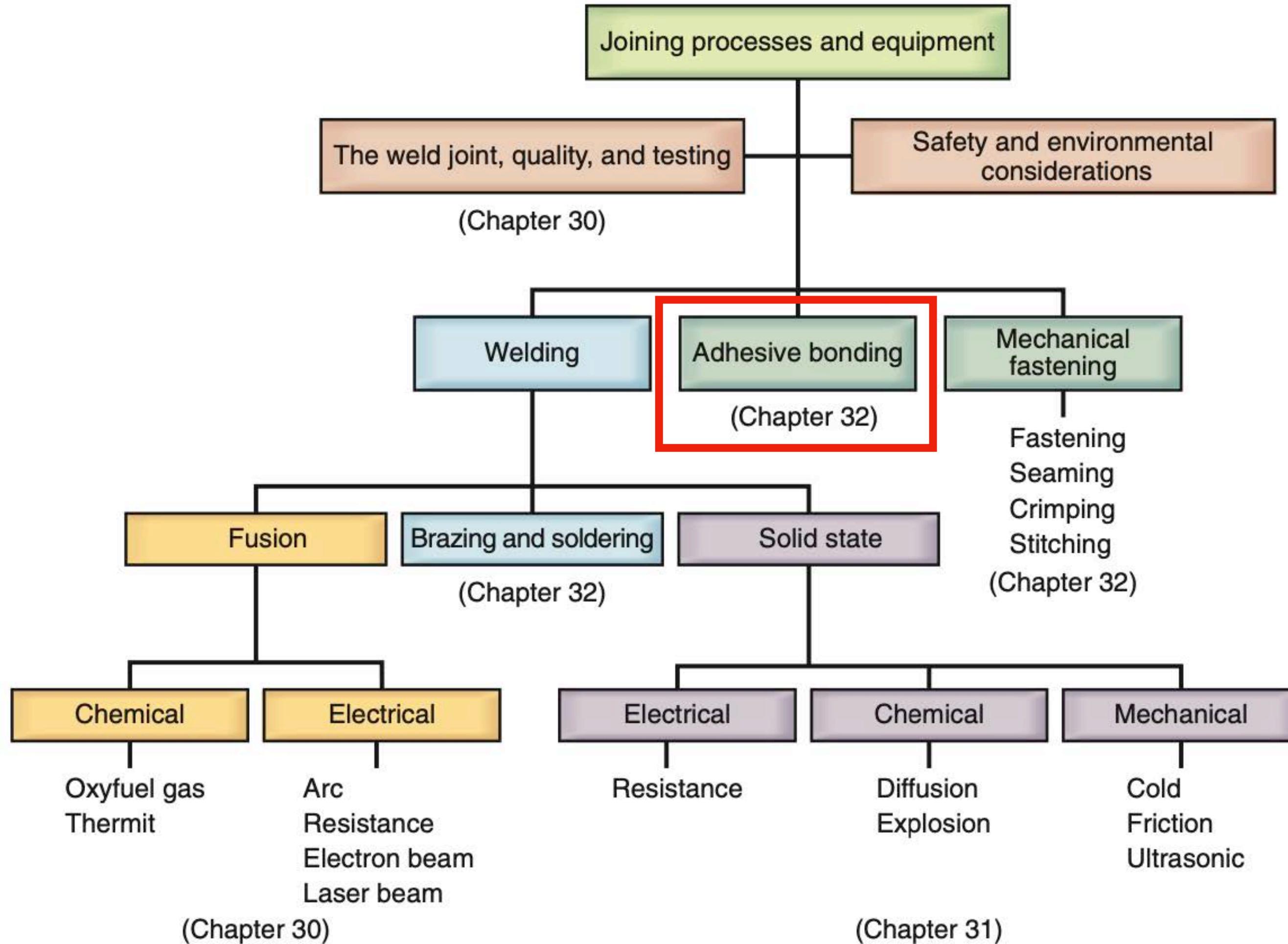


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Joining Processes



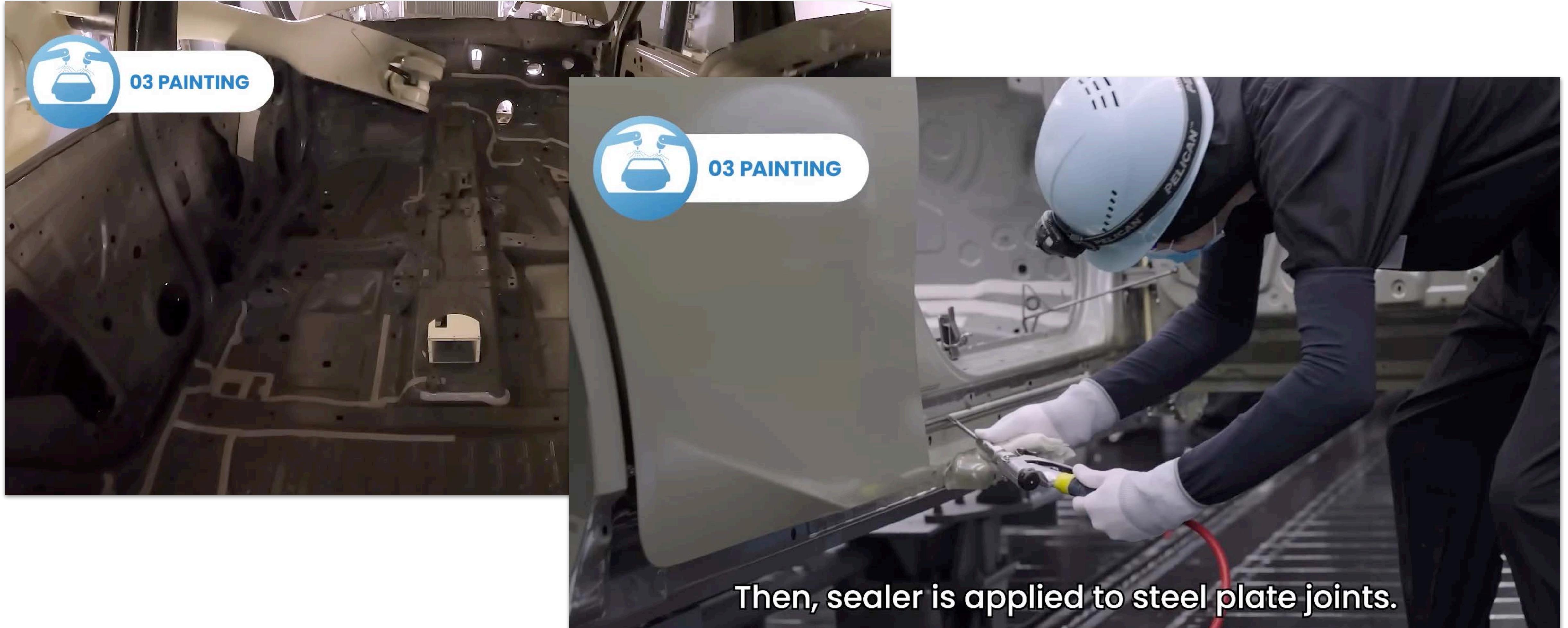
Adhesive Joining

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Adhesive Joining



Adhesive Joining



Considerations

- different materials
- easily automated
- inexpensive
- curing time limitations
- surface prep
- chemical compatibility
- strength, porosity

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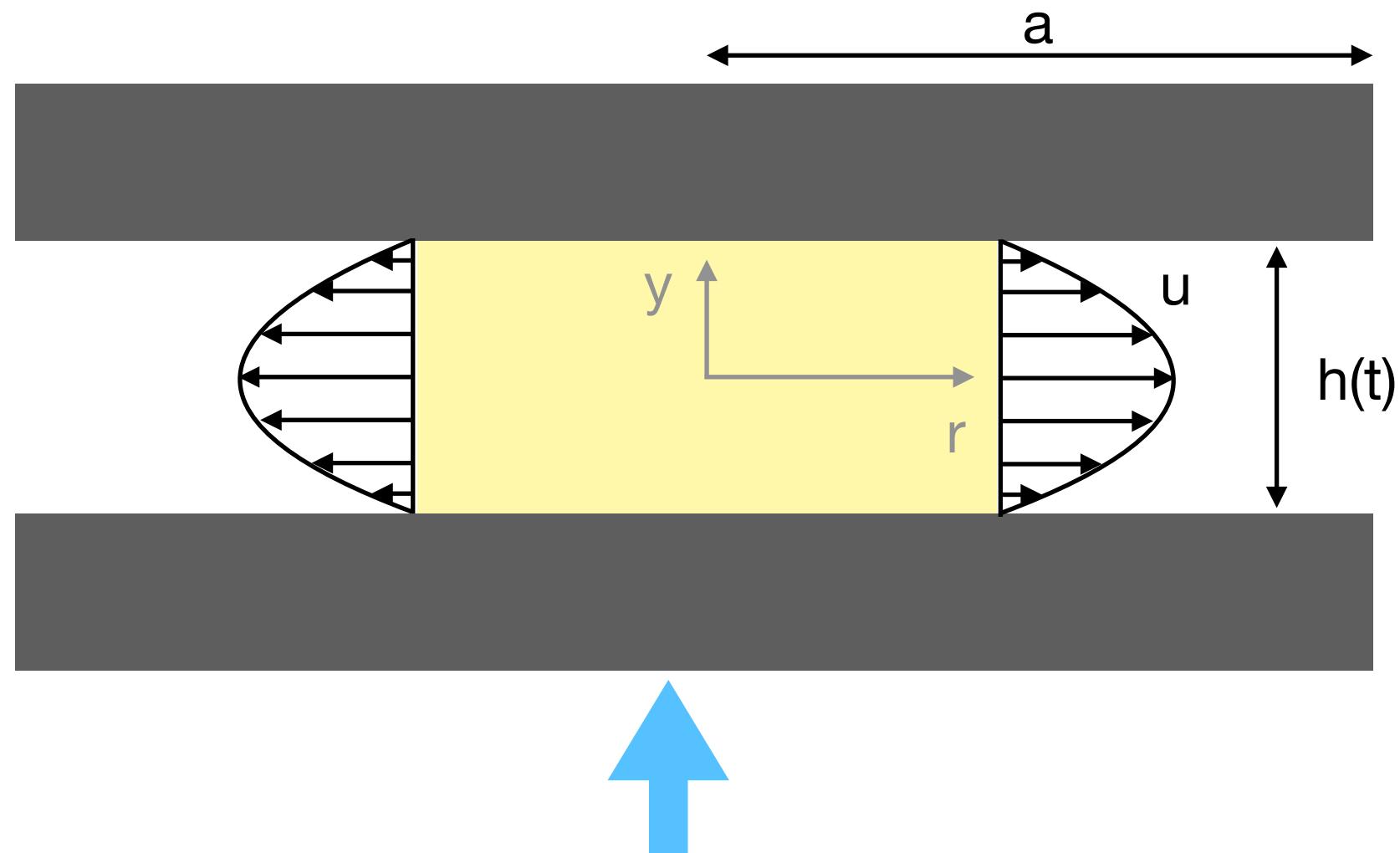
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Adhesive Joining

adhesion physics: viscosity and separation forces (demo)

Stefan Equation: apply a force over time to induce parabolic flow



$$Ft_{final} \approx \frac{3\mu\pi a^4}{4} \left(\frac{1}{h_f^2} \right)$$

μ : increases with
drying/solvent/curing

want a small gap (surface roughness/dirt can interfere)

μ : viscosity, [Pa-s]

h_i : initial gap [m]

h_f : final gap [m]

F : applied force [N]

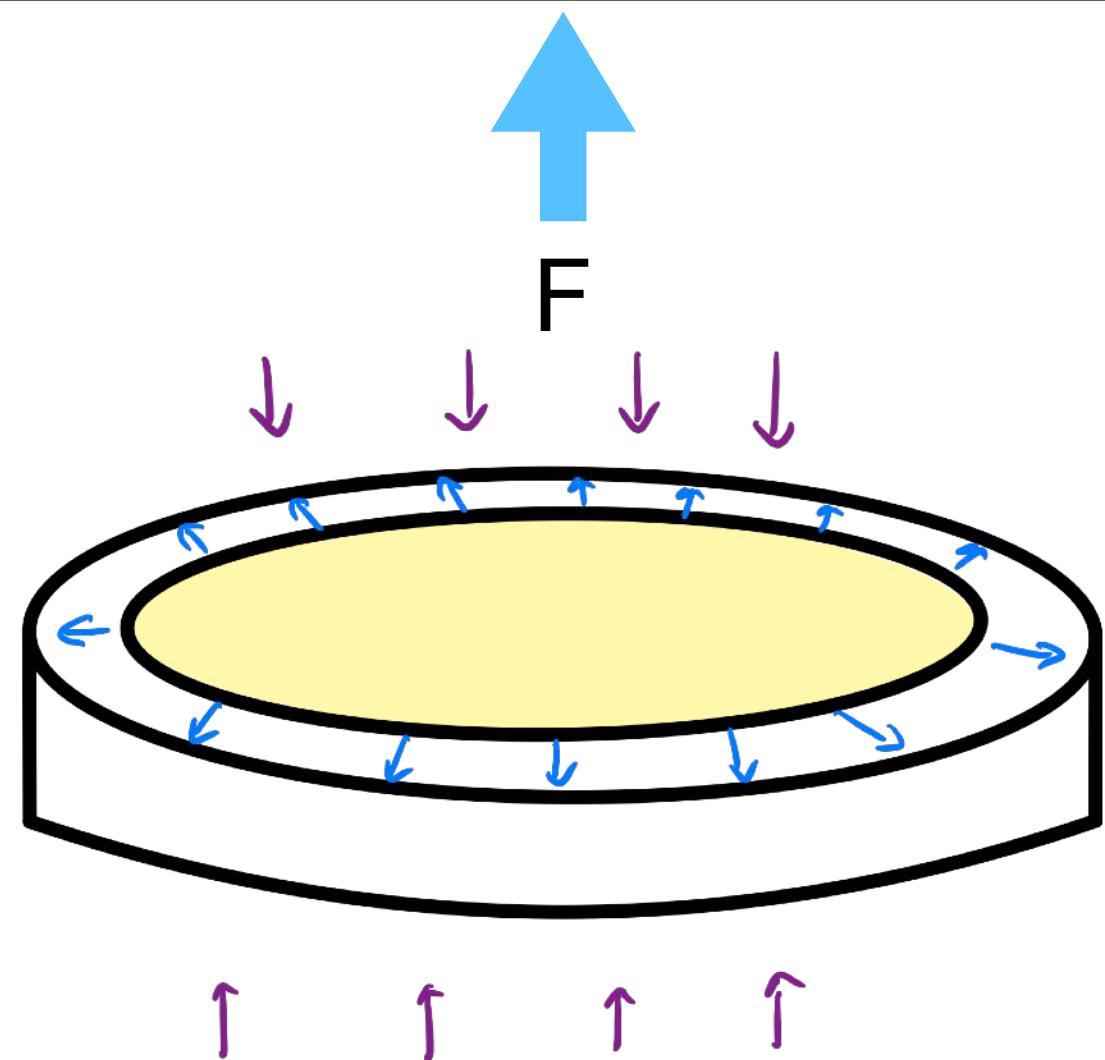
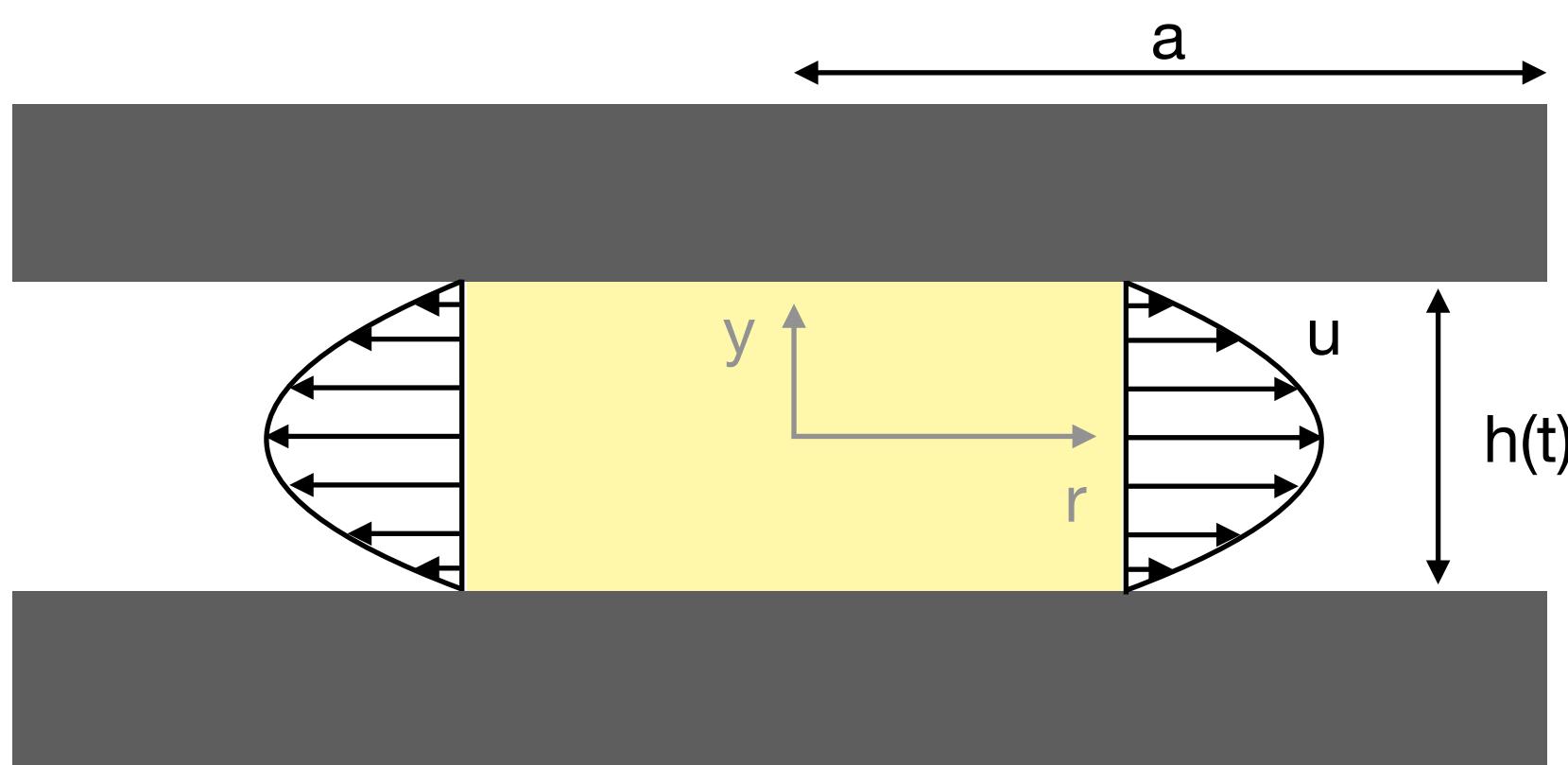
t : time [s]

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Stefan Equation Derivation



Fluid Dynamics: $u = \frac{1}{2\mu} \frac{dP}{dr} \left(y^2 - \frac{h^2}{4} \right)$

Conservation of Mass: $flow\ rate = \int_{-\frac{h}{2}}^{\frac{h}{2}} u 2\pi r dy = -\pi r^2 \frac{dh}{dt}$

substitute, integrate: $P = \frac{3\mu}{h^3} \frac{dh}{dt} (r^2 - a^2) \rightarrow F = \int_0^a P 2\pi r dr$

integrate r, t, h :

$$Ft = \frac{3\mu\pi a^4}{4} \left(\frac{1}{h_f^2} - \frac{1}{h_i^2} \right)$$

μ : viscosity, [Pa-s]
 u : velocity profile [m/s]
 h : gap height [m]
 F : applied force [N]
 t : time [s]
 a : radius of the disks [m]

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Adhesive Joining

cohesion (like molecules) vs
adhesion (different molecules)

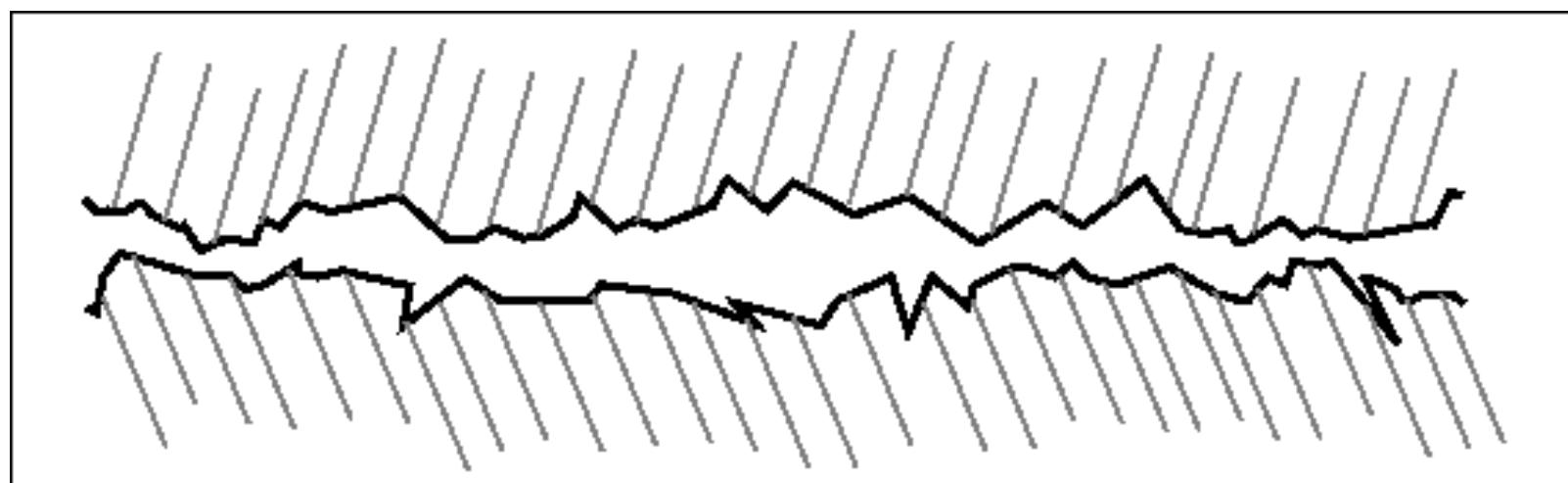
types of surface interactions

mechanical

chemical

electrostatic (Van der Waal's)

diffusion



epoxies: thermoset polymers
that cross-link while curing

PVA (polyvinyl acetate) + water
(similar to wood glue)



latex (rubber) in a solvent
application with flexibility



cyanoacrylate reacts to
moisture in air (org. medical)

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Adhesive Joining



solvent that chemically melts and reforms plastic, creating new molecular bonds



spray adhesive for fast, wide application



thermoset that also can react with moisture in air, inert sealer
(urethane glue also reacts to moisture or is two part)



hot melt glue transitions with heat

Joining II

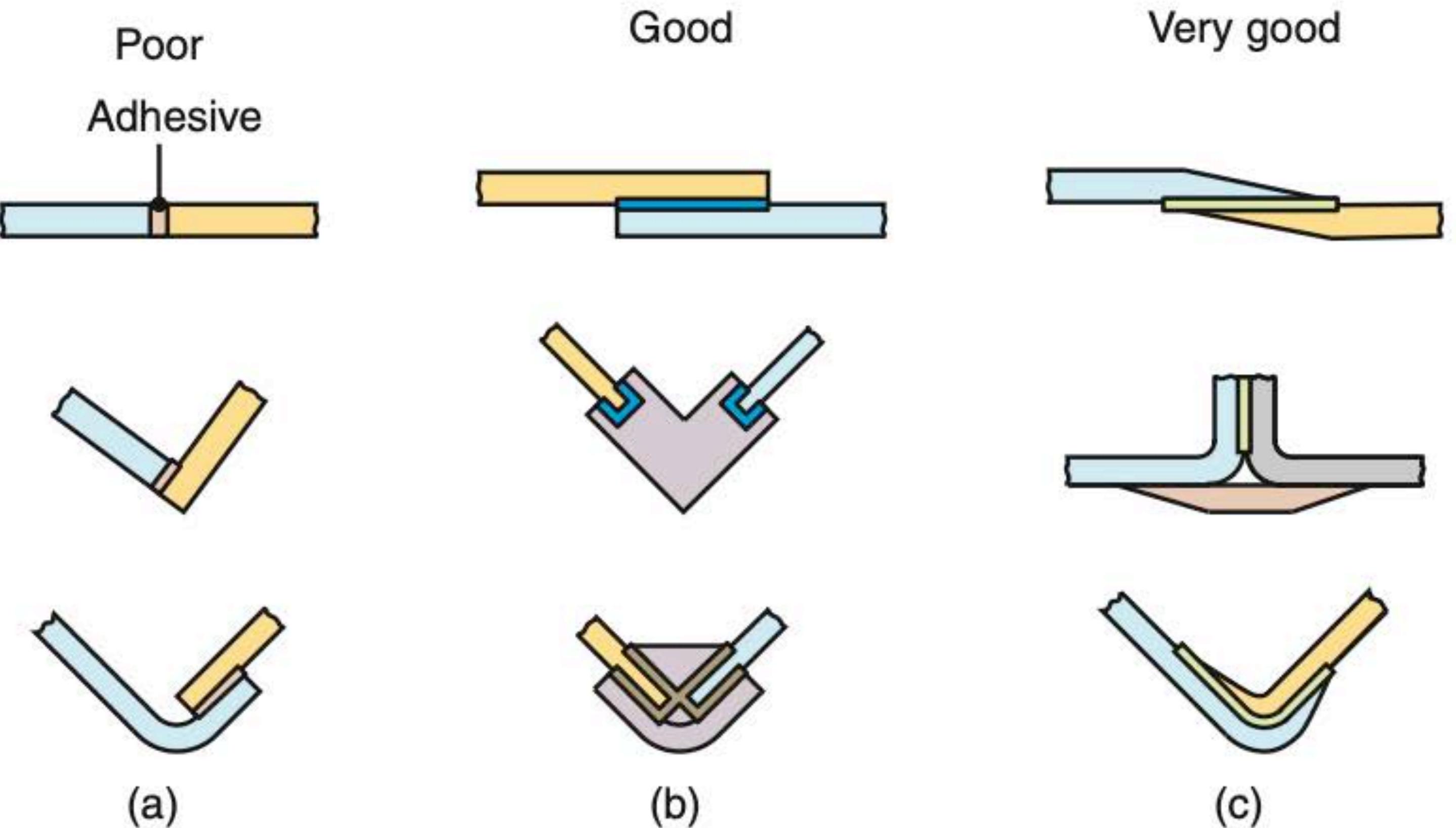
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DF: Adhesive Joining

match loading type between design and adhesive choice

large contact area is best

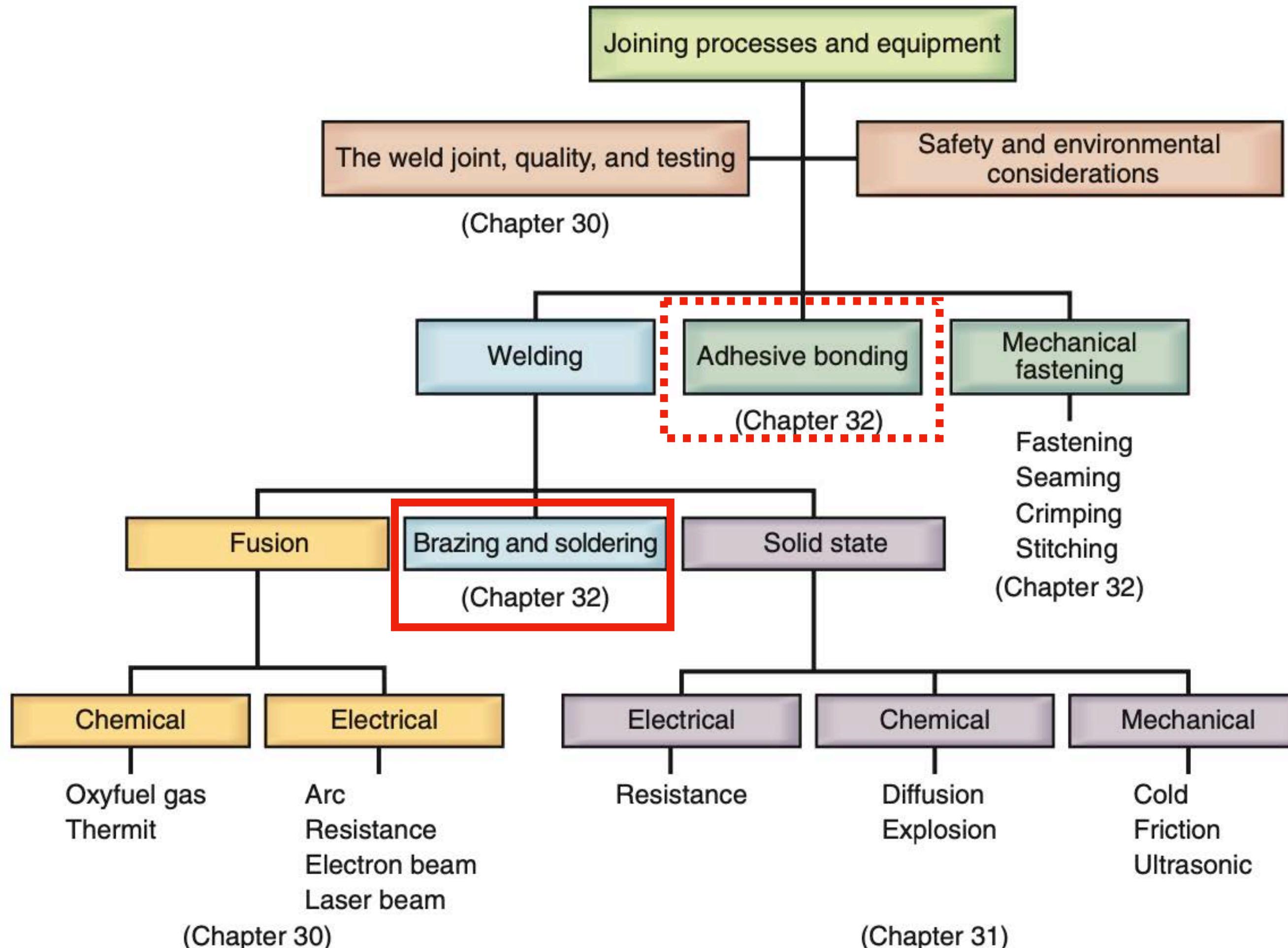


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Joining Processes



Brazing and Soldering

filler metals are melted and used to fill the gap

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Processes and Types

Brazing and Soldering

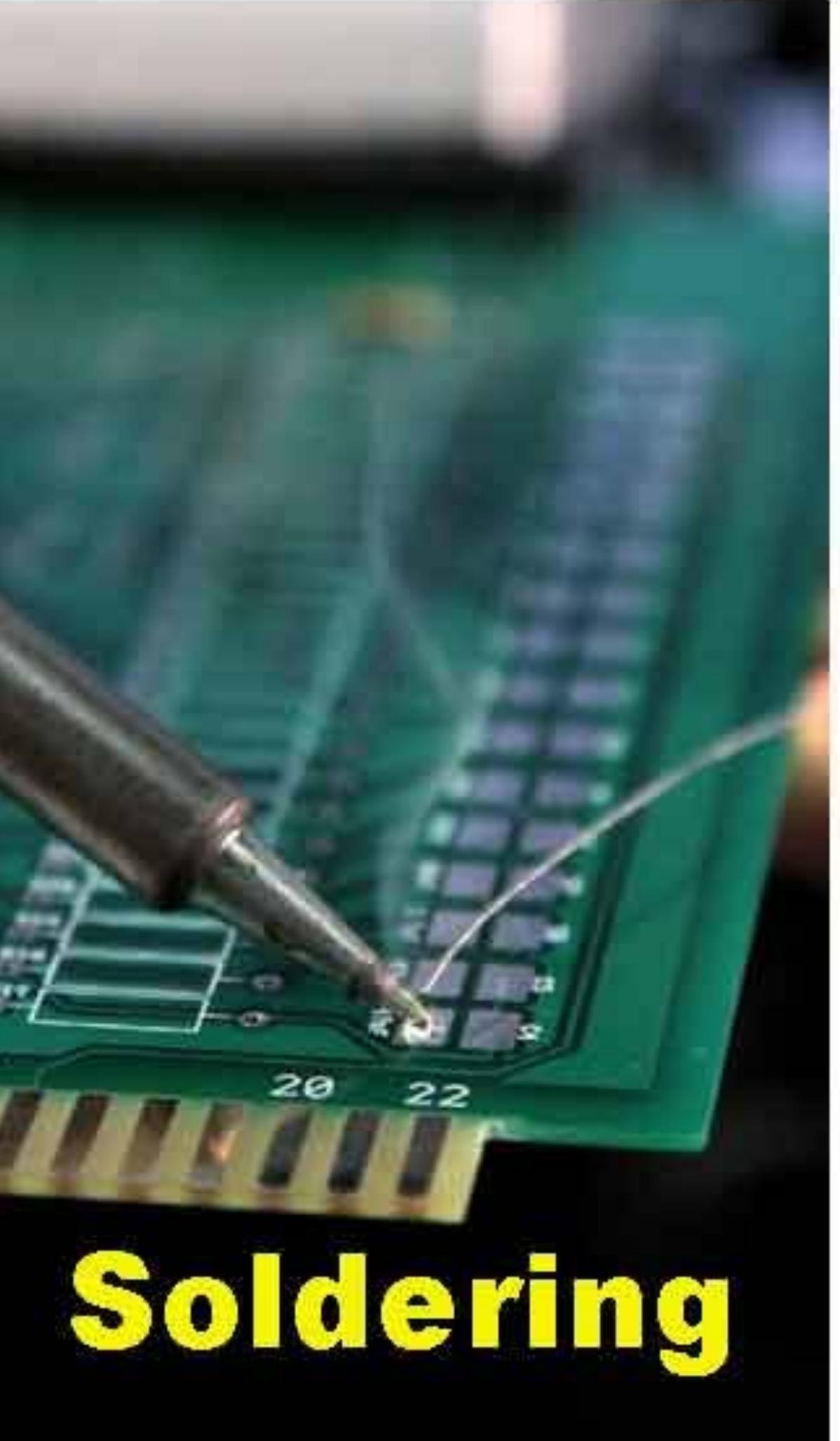
same process at different temperatures

electronics, plumbing, jewelry, structural

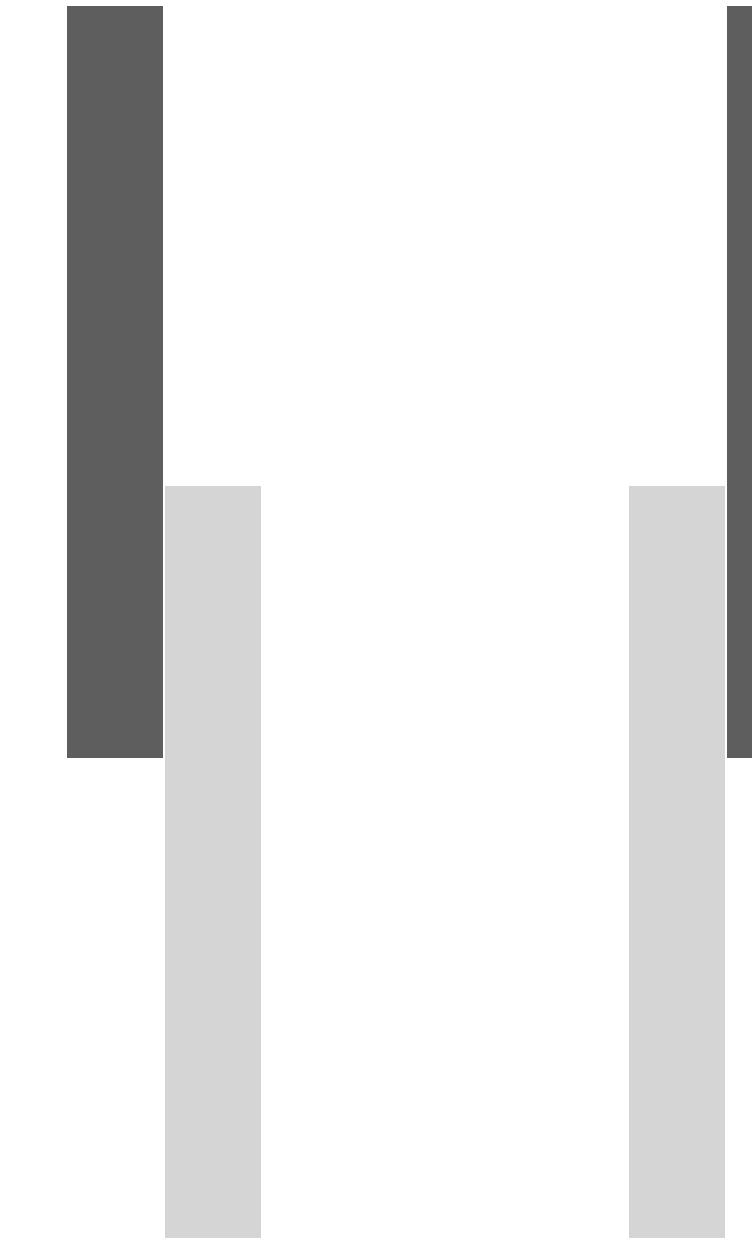
above 450°C (840°F) is brazing (e.g. Silver, Brass)

below is soldering (e.g. Tin/Lead)

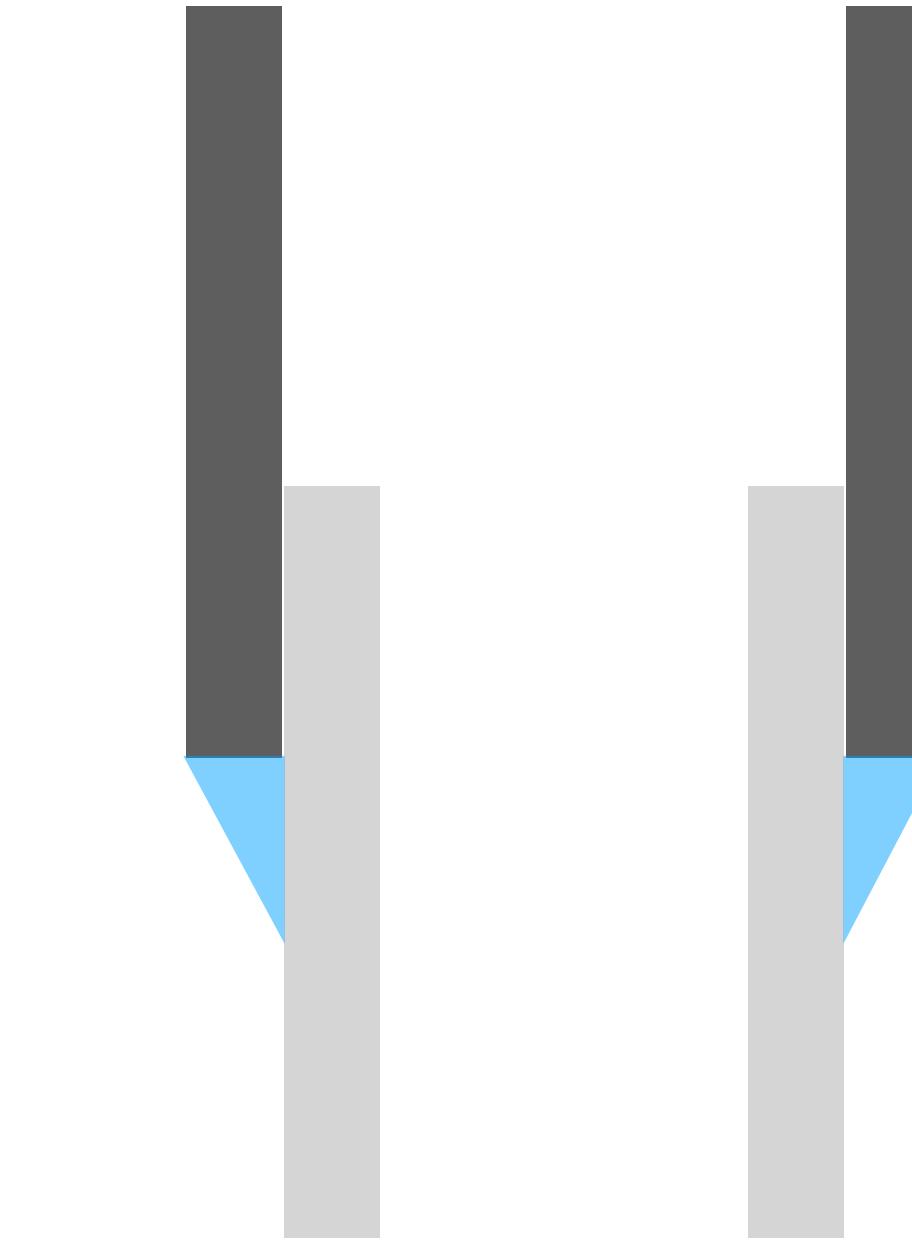
liquid-solid-state bonding (+ dissimilar metals)



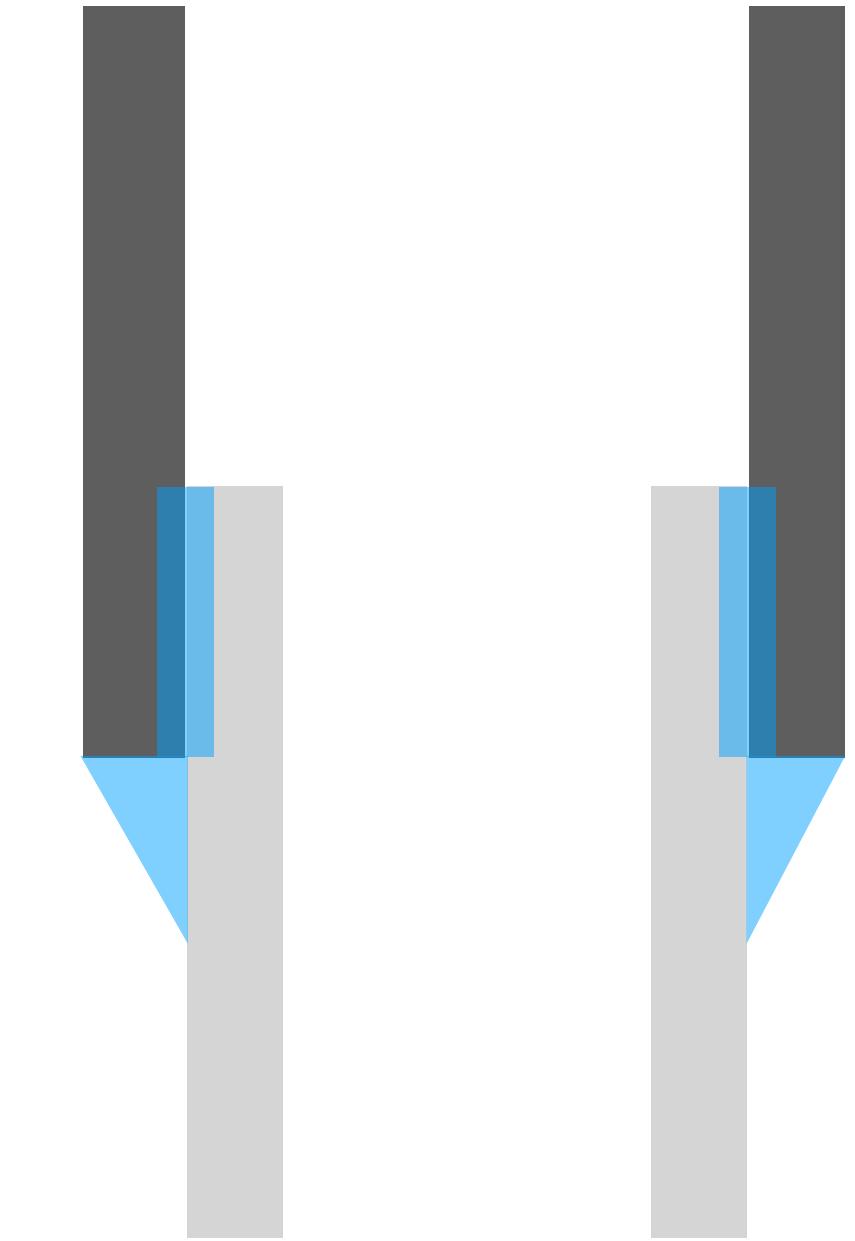
Brazing and Soldering: Capillary Forces



1. two pipes to be joined



2. introduce liquid filler



3. surfaces joined
(strong in shear)

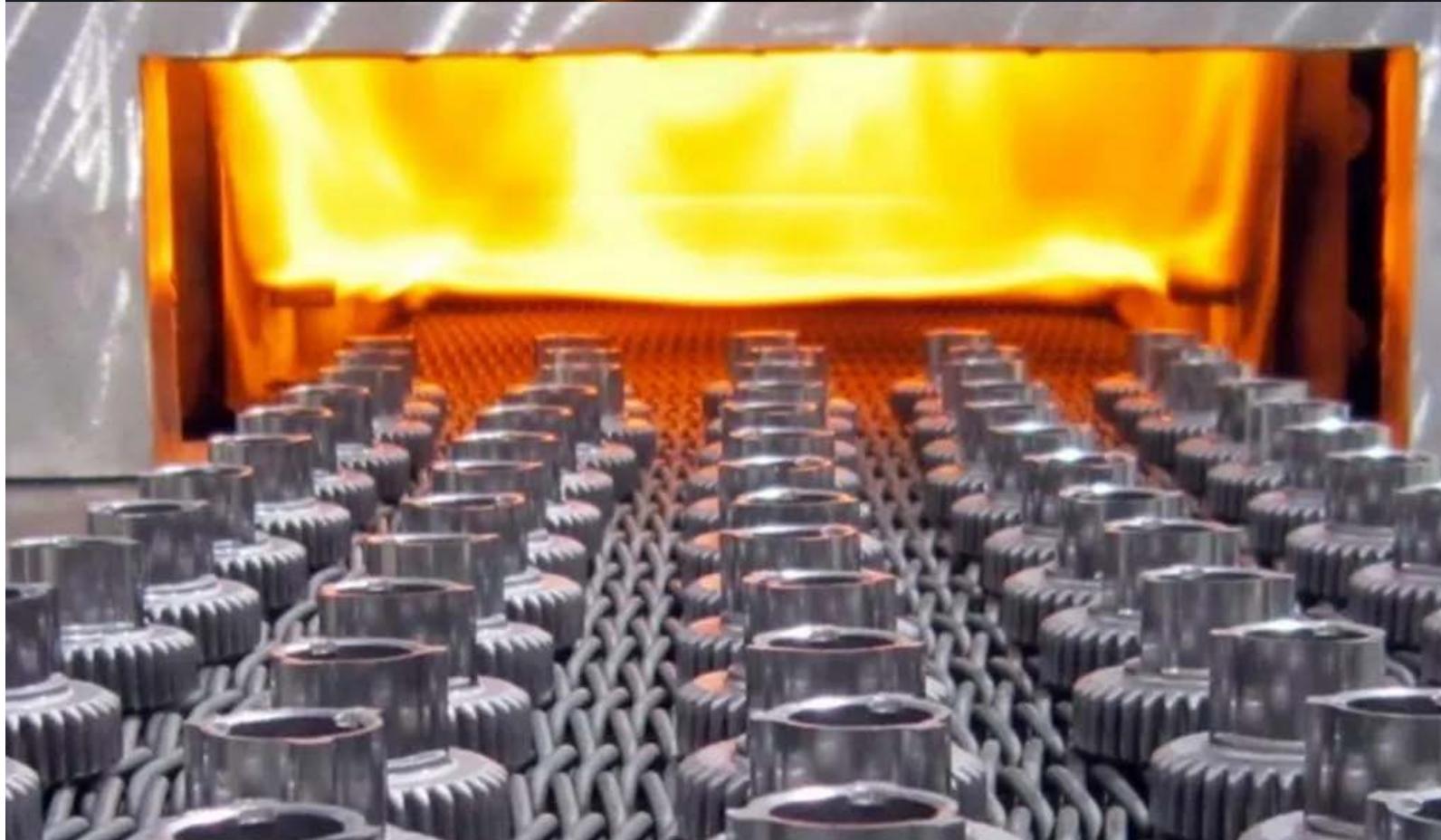
demo: surface preparation

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Brazing and Soldering



Processes

torch (oxyacetylene)

furnace

induction

resistance

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Brazing and Soldering

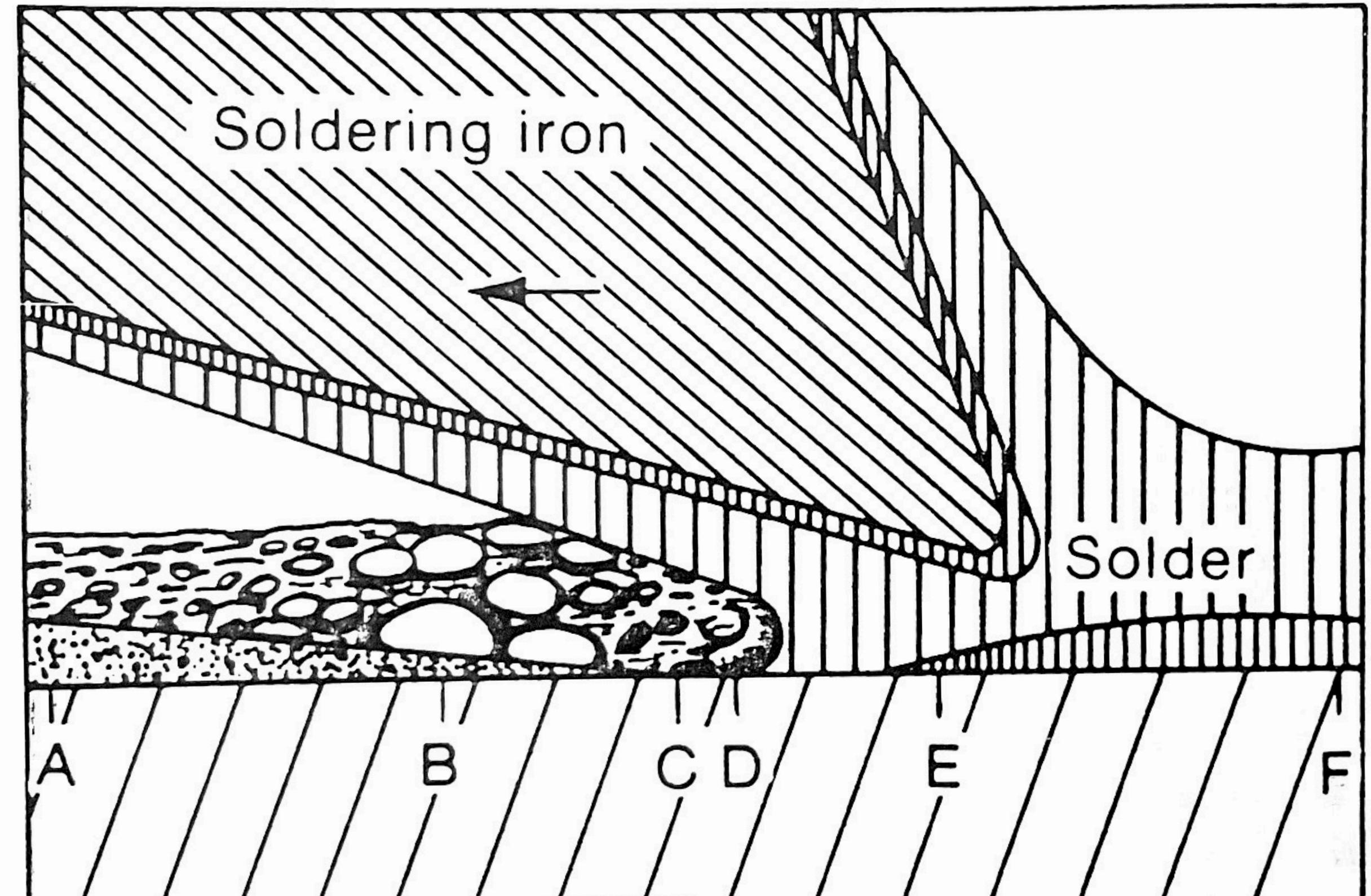
purpose of flux

removes oxides (protects from oxidation)

improves surface wetting

process

- A. Flux on top of oxidized metal
- B. boiling flux removes oxide
- C. base metal in contact with molten flux
- D. molten solder displaces molten flux
- E. solder adheres to based metal
- F. solder solidifies



← Direction of movement of
soldering iron

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Brazing and Soldering

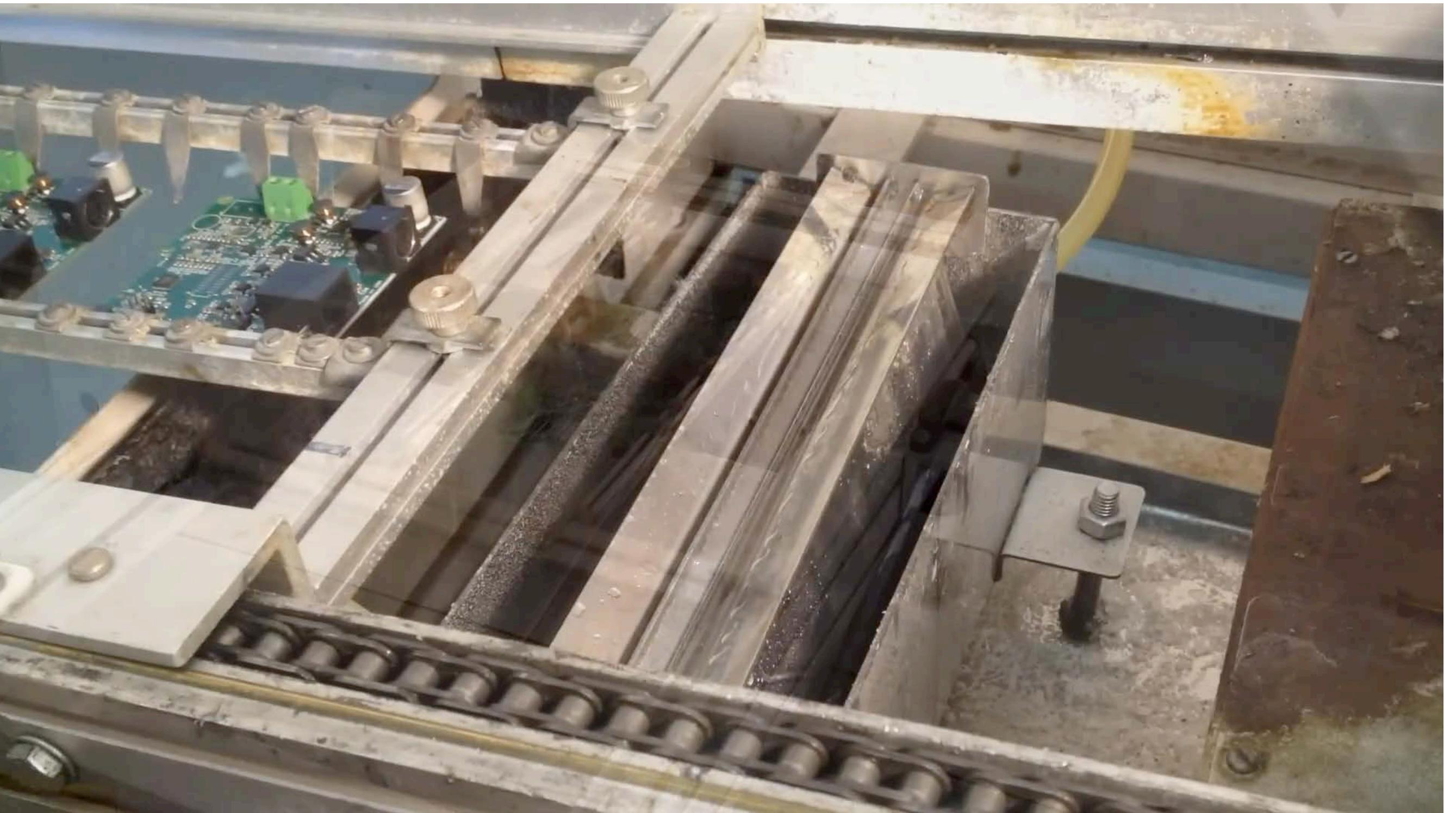
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Processes and Types

DF: Brazing and Soldering

filler metal should have good “wetting” characteristics

joined surfaces should not be smooth

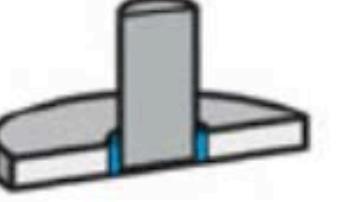
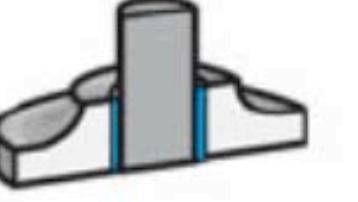
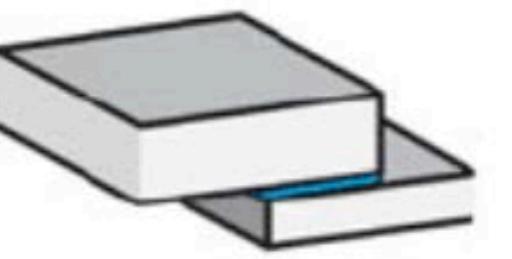
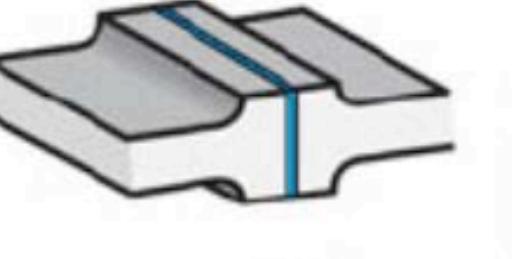
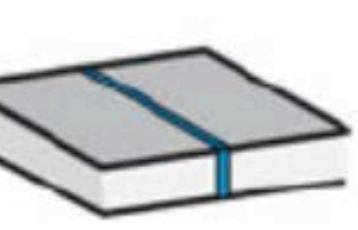
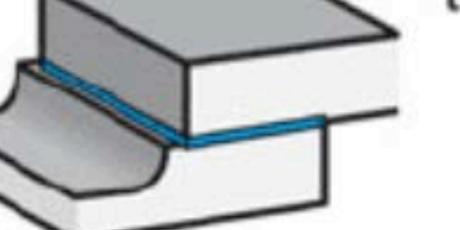
Poor	Good	Comments
		Too little joint area in shear
		Improved design when fatigue loading is a factor to be considered
		Insufficient bonding area

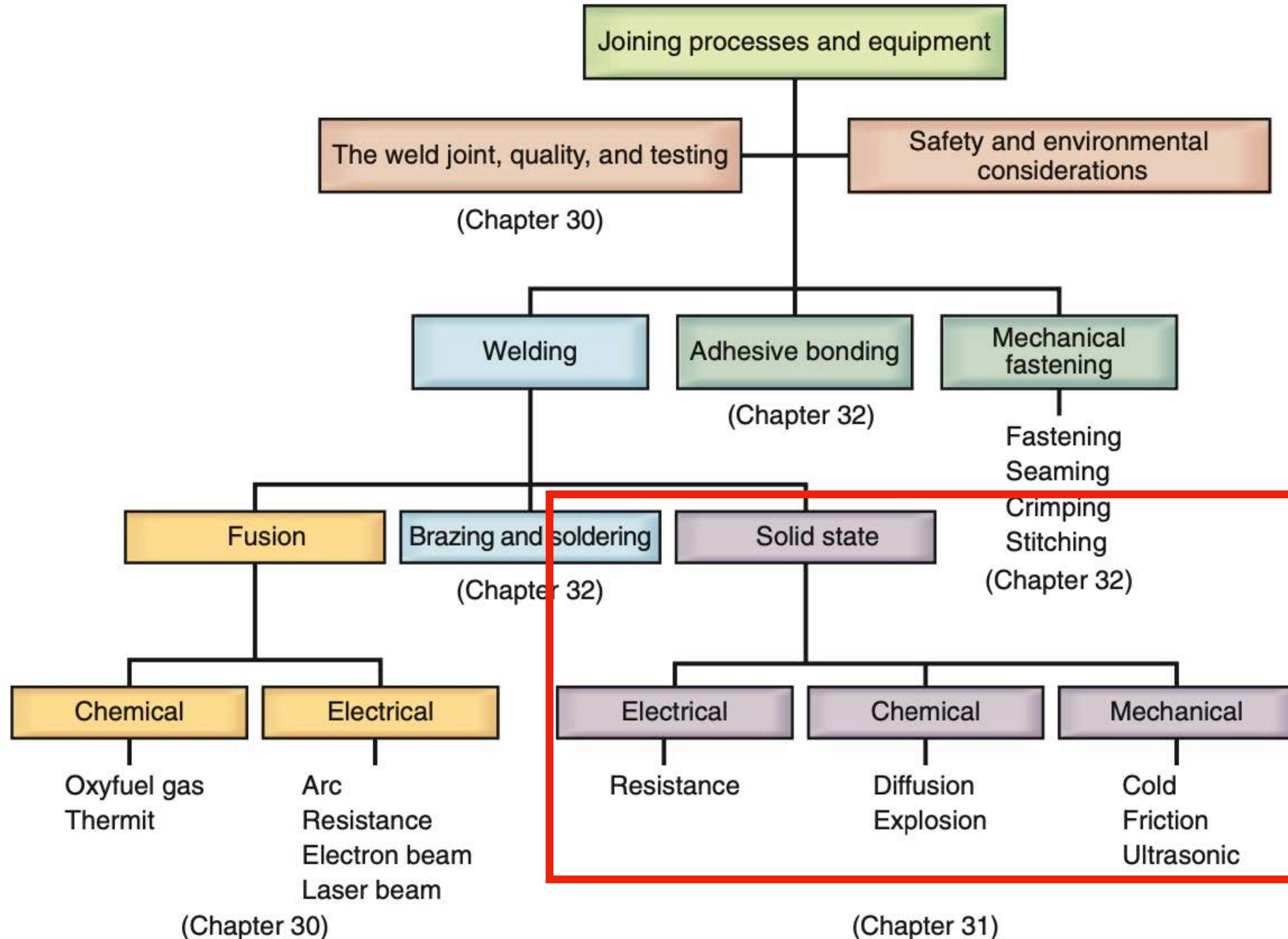
FIGURE 32.6 Examples of poor and good designs for brazing. *Source:* American Welding Society.

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Joining Processes



Solid State (Interatomic) Processes

no third material: just bonding one material directly to another

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Processes and Types

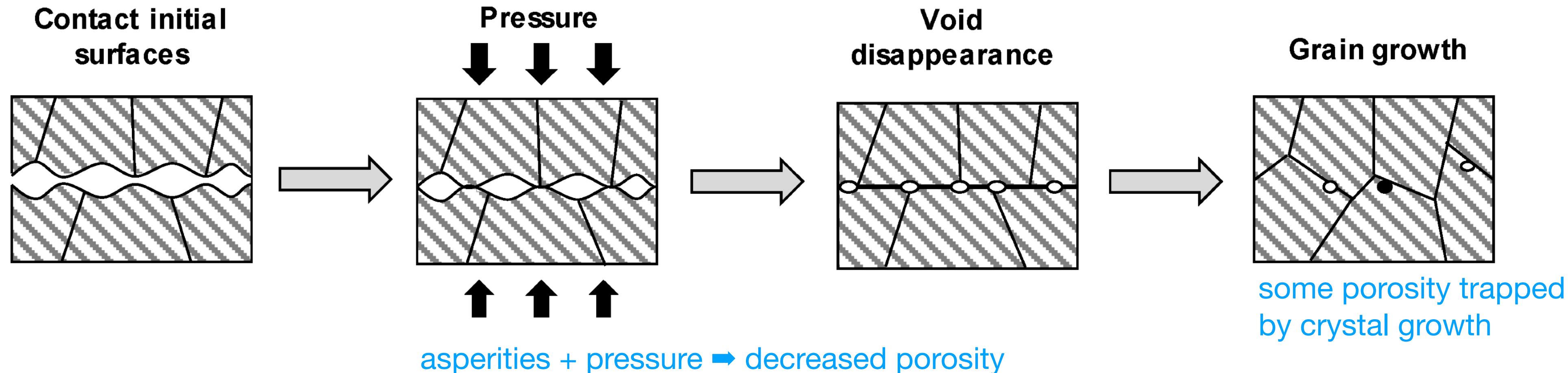
Diffusion Bonding

materials “grow across to each other”

typically at temperatures of $2/3 \times T_{melt}$, pressures of 500 to 5,000 psi

expensive: aerospace,
not automotive

surface quality/finish matters



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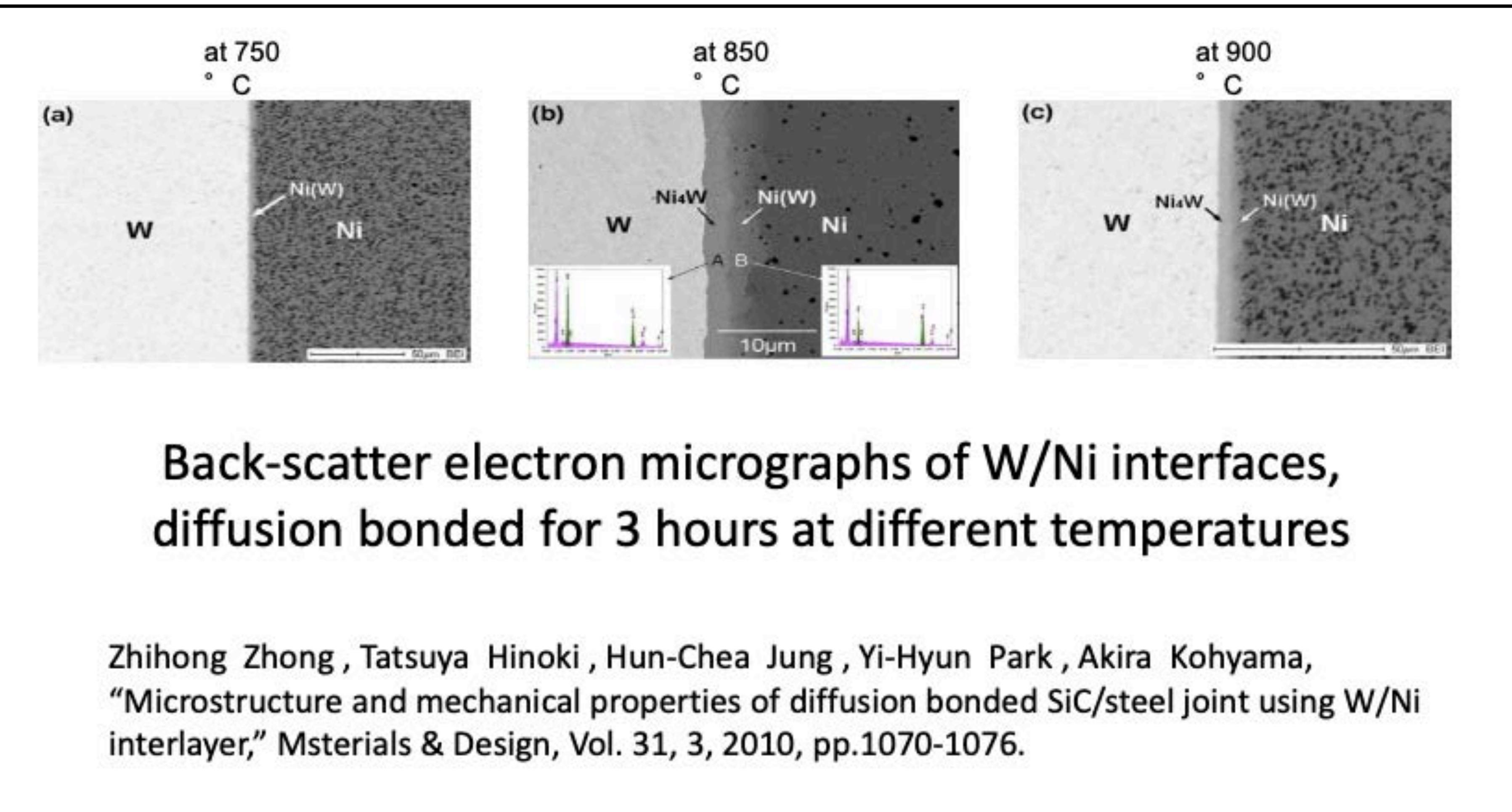
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Diffusion Bonding

Nickel and Tungsten **react to each other**, otherwise you might need a film of another metal to facilitate bonding

gradient of material is formed



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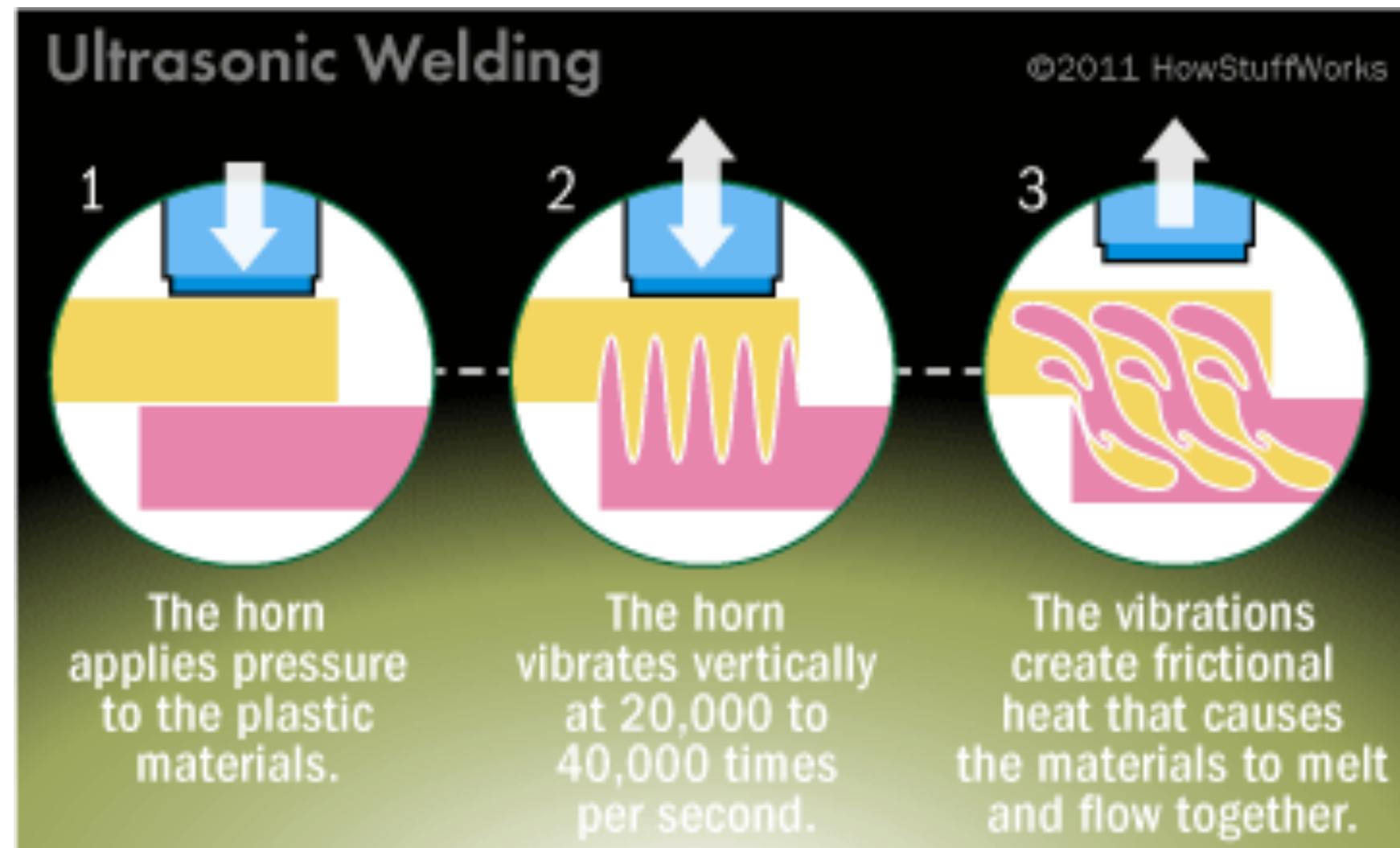
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Other Solid State Processes

Ultrasonic Welding

shear at 10-75 kHz vibration



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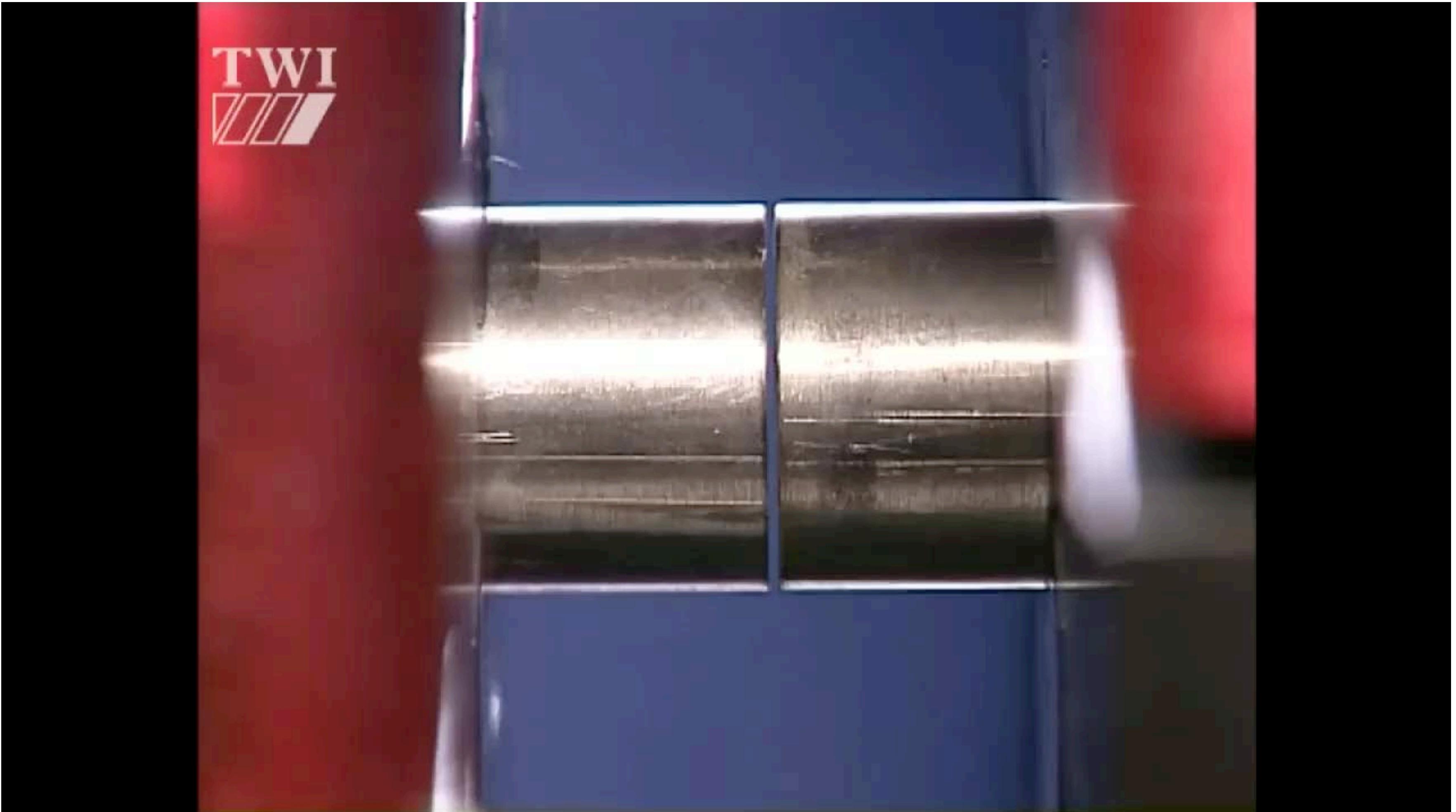
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Other Solid State Processes

Friction Welding

material surfaces sheared
against each other

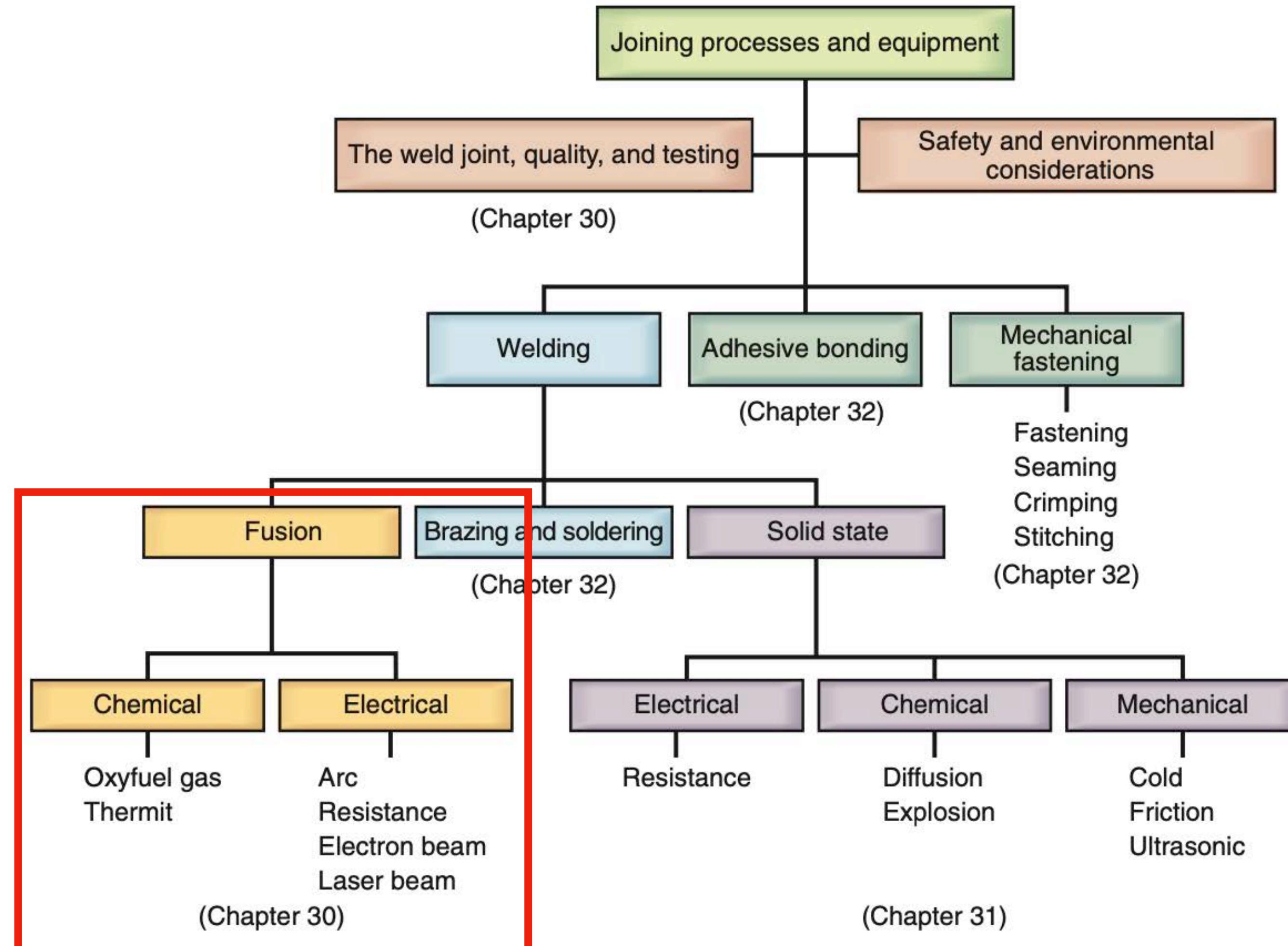


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Fusion Welding

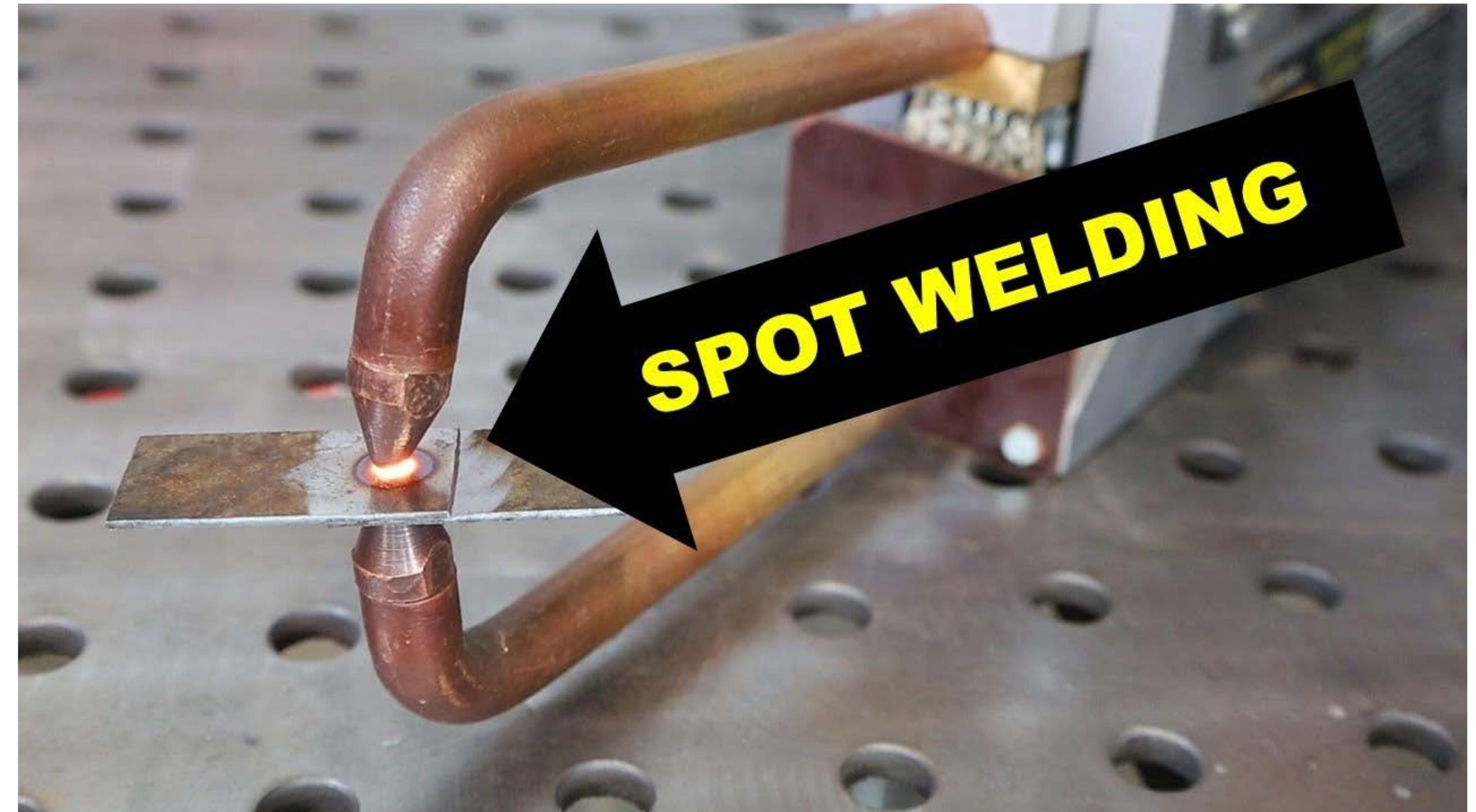
melting occurs at the interface

Fusion Welding

different examples of welded parts

spot welding: based on electrical resistance

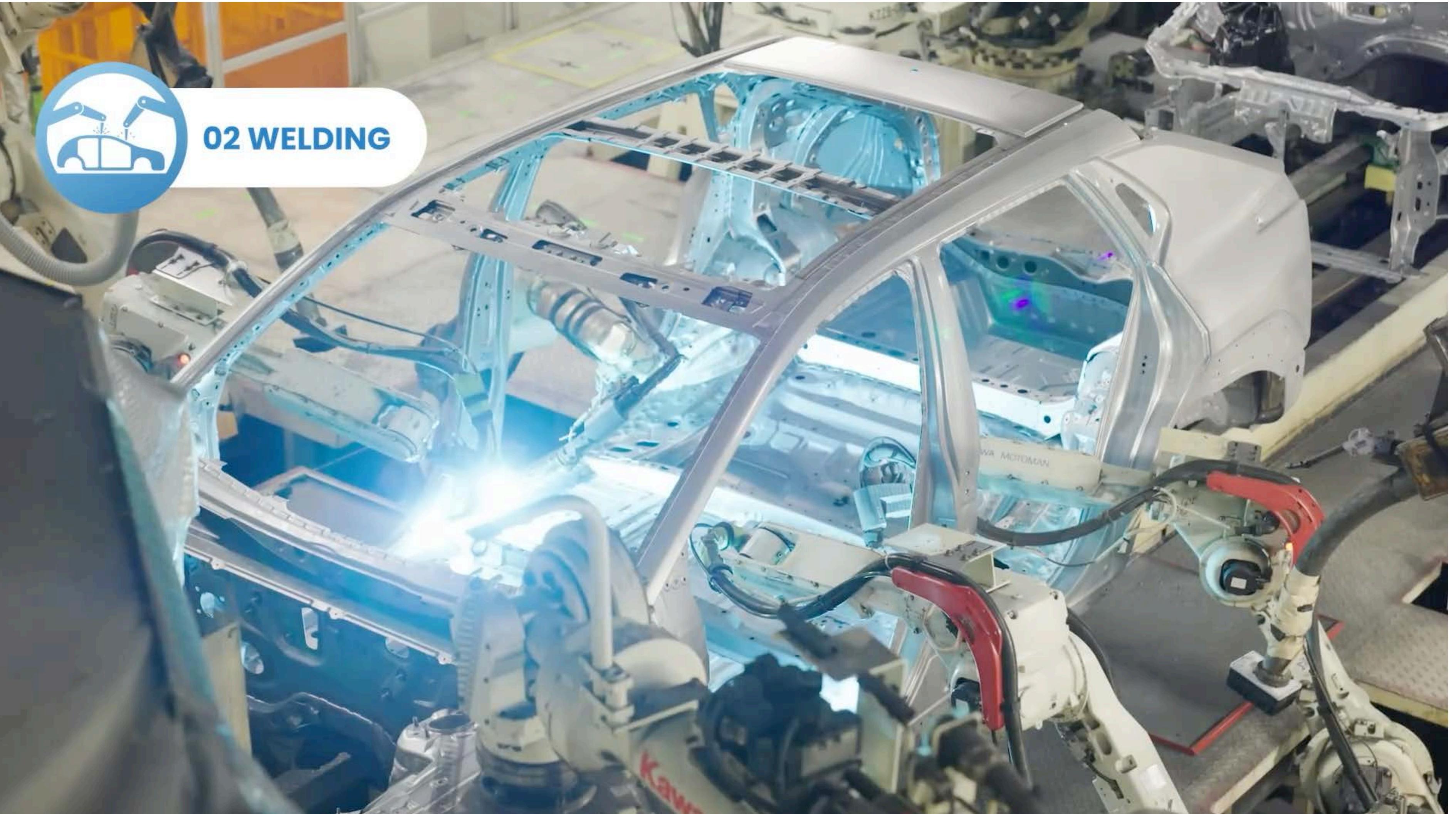
resistance of the interface is highest: melts there first



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Fusion Welding

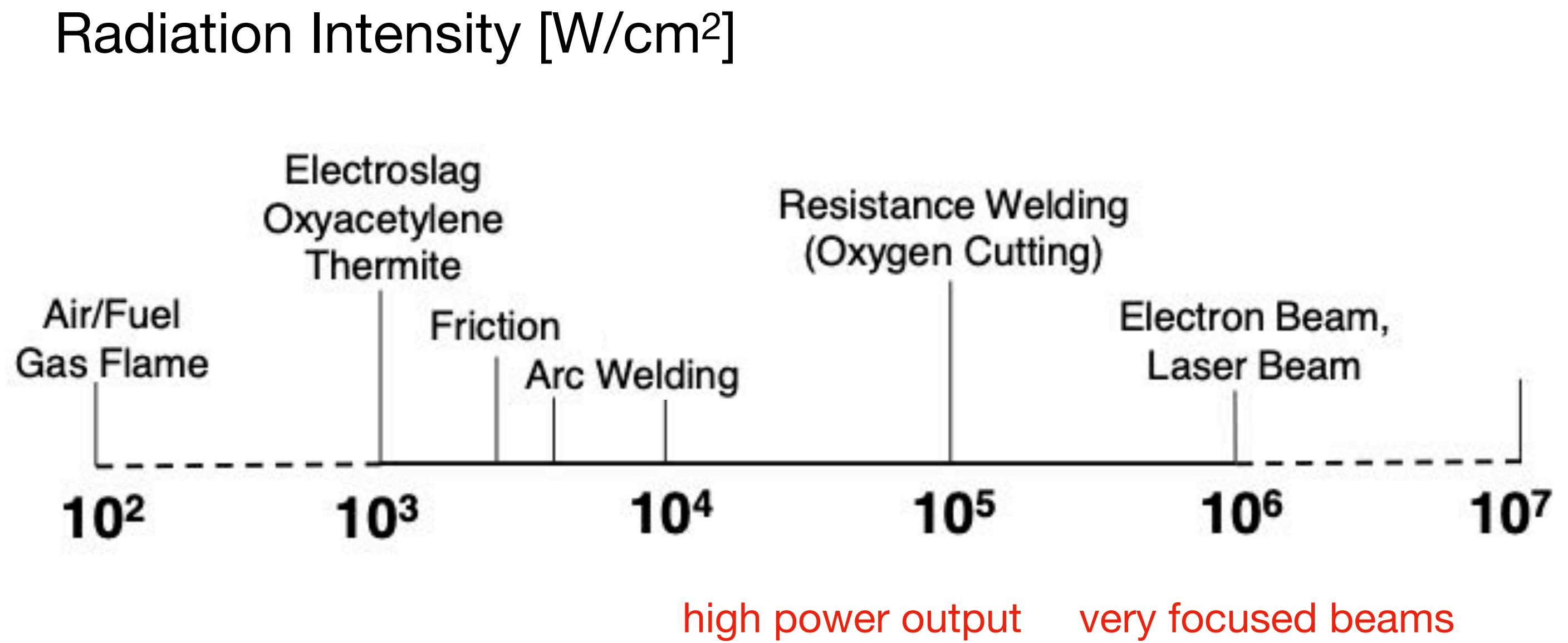


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Fusion Welding



more intense source → faster melting, but it's easy to over melt!

automation is essential for controlling the process

Heat Intensity Considerations

over melting, evaporation
heat affected zone (HAZ)
change in properties
efficiency
lower intensity, slow down...
heat small area quickly
depth/width ratio
more intense: penetrate deeper without width

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Melt Pool Depth

How fast do you have to move?

Jakob #

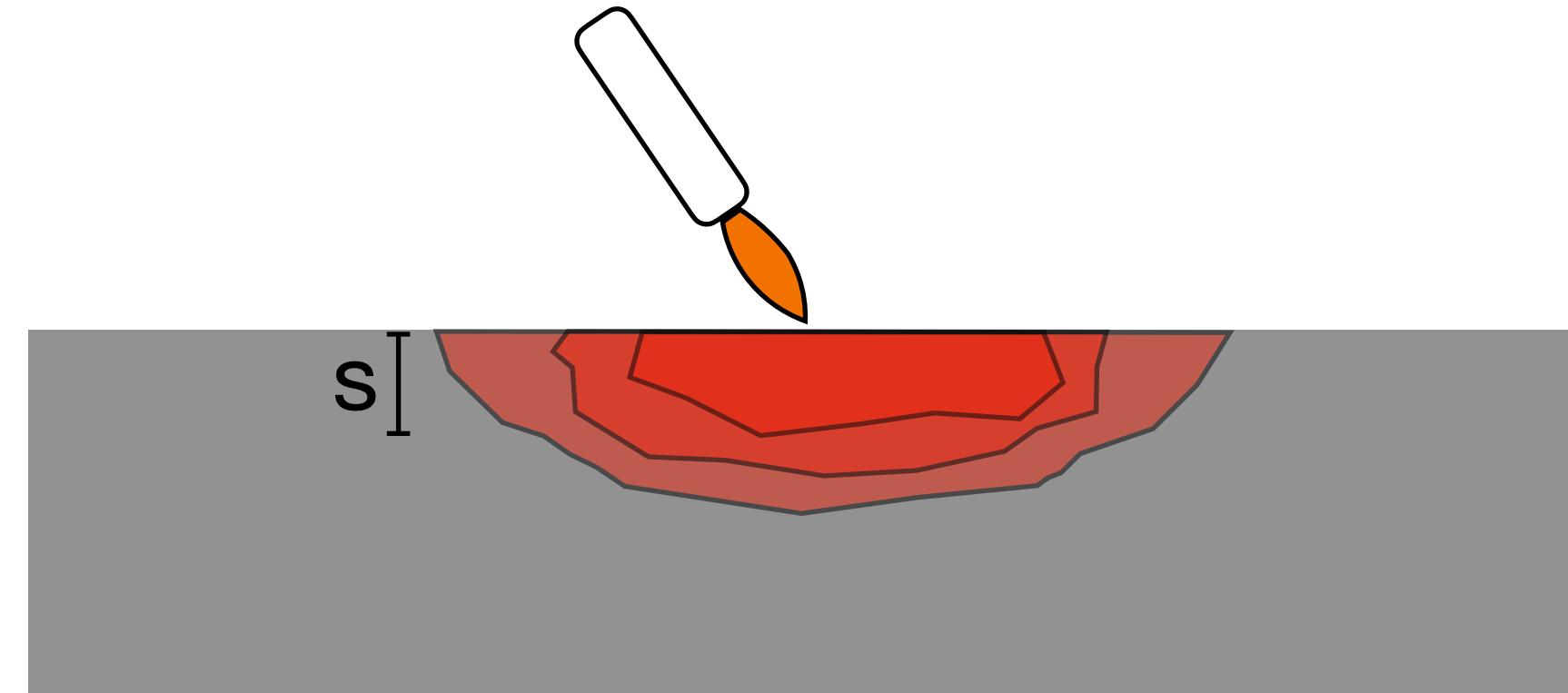
$$J = \frac{c_p(T_{melt} - T_{initial})}{h_{fs}}$$

energy to get to melt temp
energy to convert to liquid

thermal diffusivity

$$\alpha = \frac{k}{\rho c_p}$$

c_p : specific heat capacity [J/kg°K]
 T_{melt} : melting temperature [°K]
 $T_{initial}$: starting temperature [°K]
 h_{fs} : specific latent heat of fusion [J/kg]
 k : thermal conductivity [W/mK]
 ρ : density [kg/m³]
 s : melt pool depth [m]
 t_{max} : time to reach depth s [s]



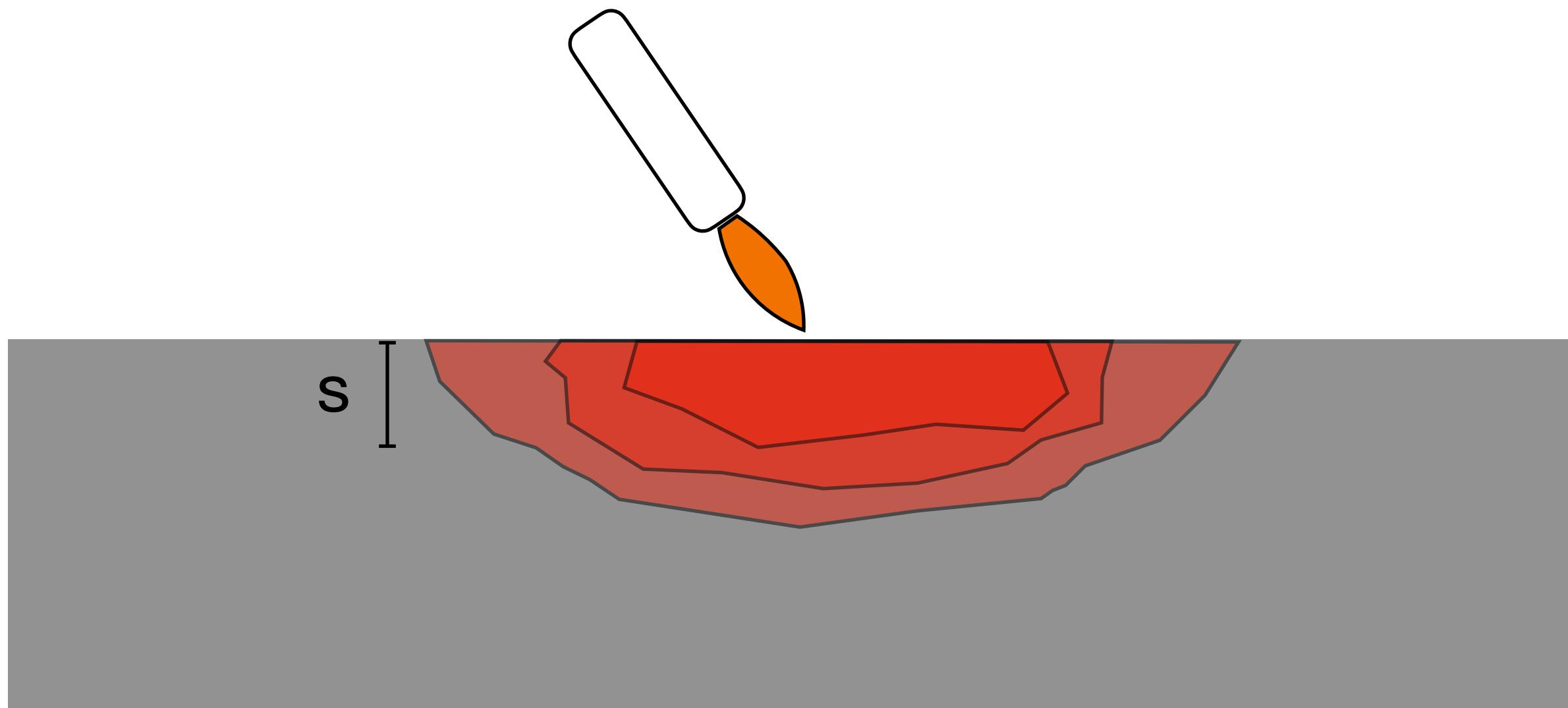
$$s \approx \sqrt{2 \alpha J t_{max}}$$

depth of melt pool over time, so:

$$t_{max} \approx \frac{s^2}{2\alpha J}$$

stay any longer, and you will over-melt!

HAZ: Heat Affected Zone



region near the weld pool is affected by heat

the microstructure changes

the size of the HAZ is controlled by the thermal diffusivity α

why α ? \downarrow α means more localized heating

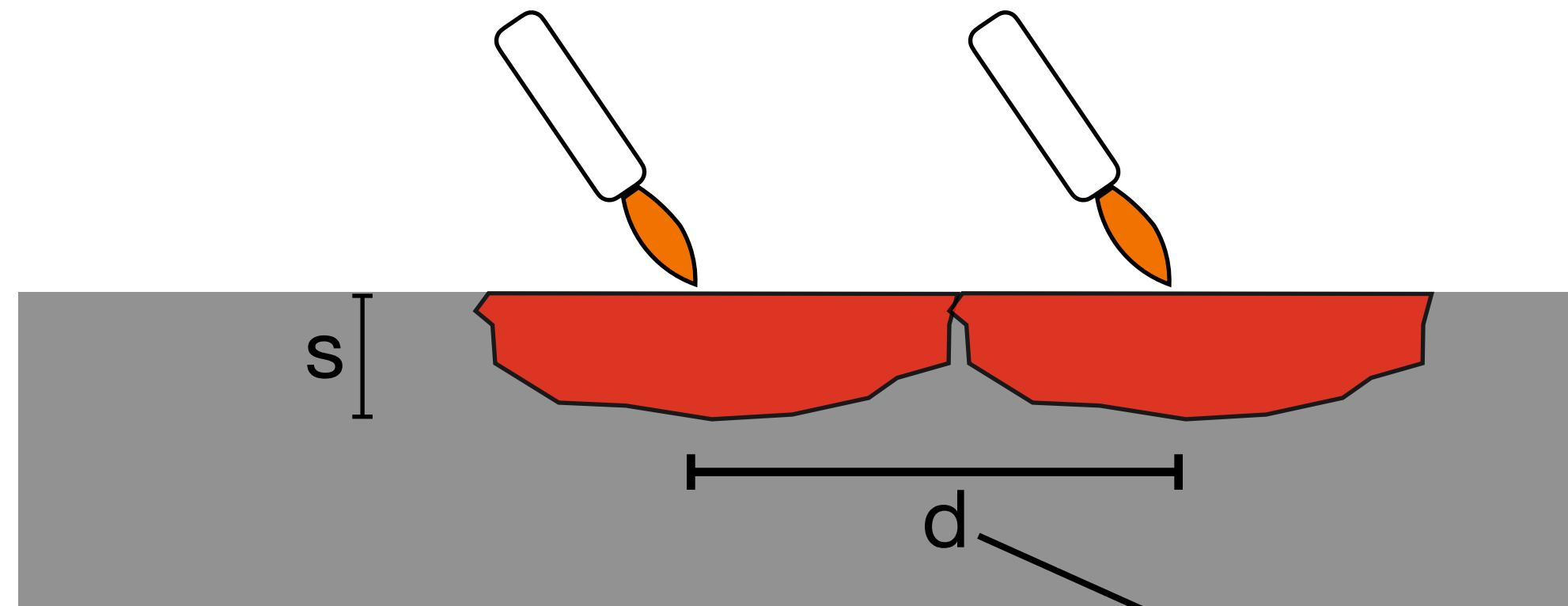
soldering iron on plastic: small weld pool

on metal, you heat the whole piece!

lower heat intensity takes longer: allows for more time to diffuse

you want high intensity with less time to diffuse: more efficient (faster) and more localization (no over-melting)

Melt Front Velocity



$$t_{max} = \frac{s^2}{2\alpha J} \rightarrow v_{min} = \frac{d}{t_{max}}$$

Welding Rate

the rate at which the welding device must be moved is governed by:

the Heat Intensity: the greater the intensity, the faster the device must move to keep the melt depth s constant

αJ : the larger this product, the faster the melt front moves

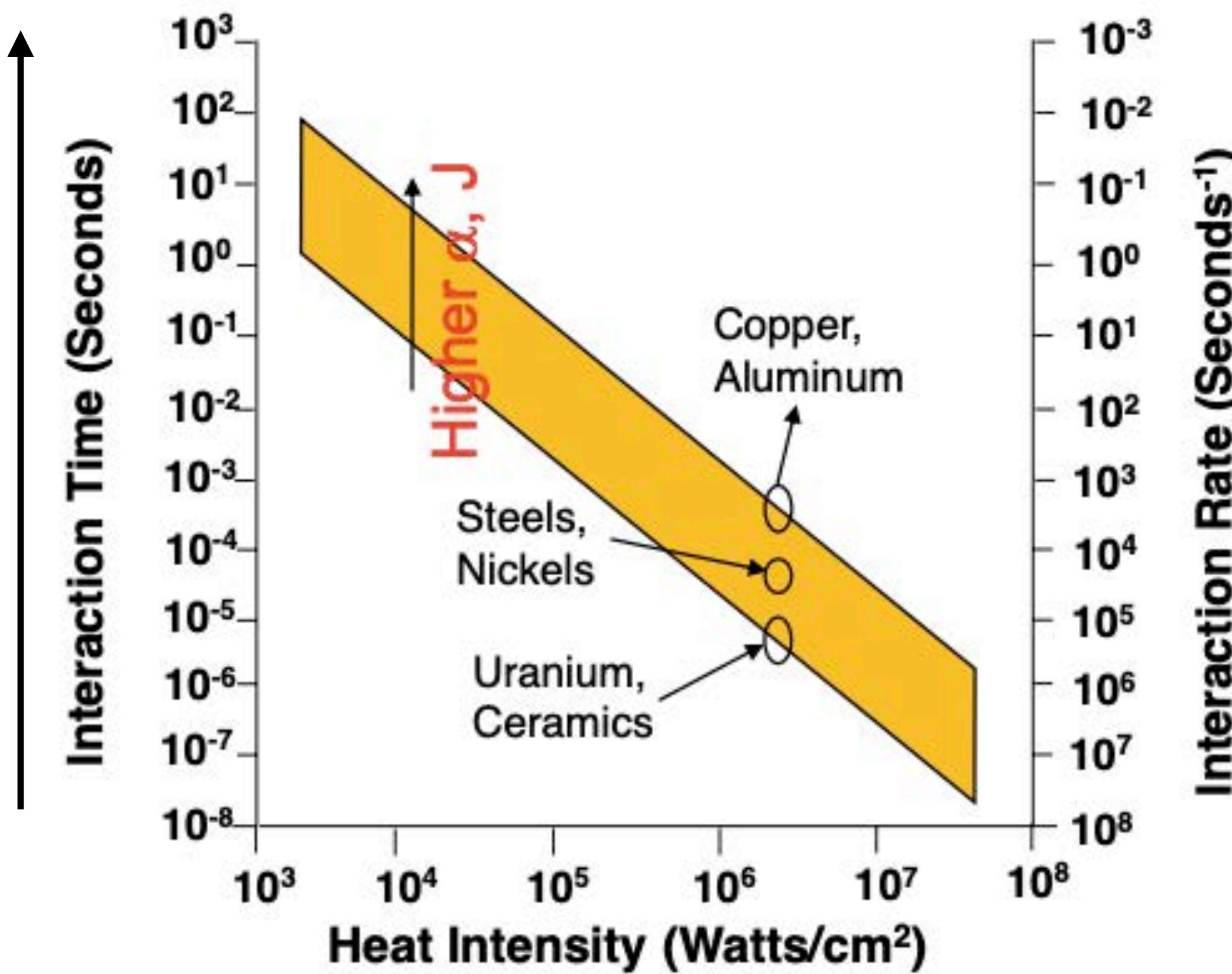
you need to feed at least this fast to prevent over melting

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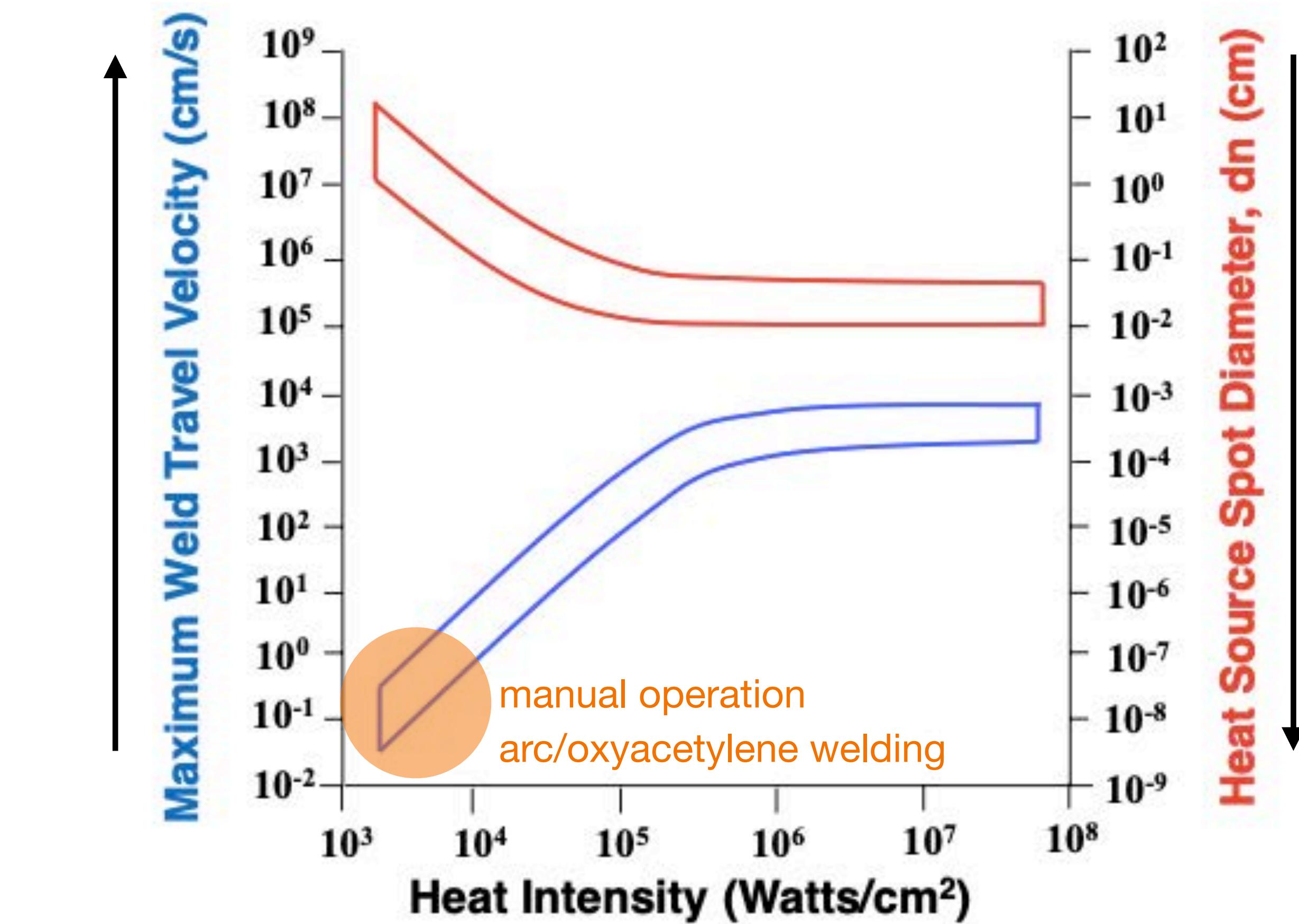
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Weld Pool: Heat Source Interaction Time



Weld Velocity



Main factor : Thermal diffusivity

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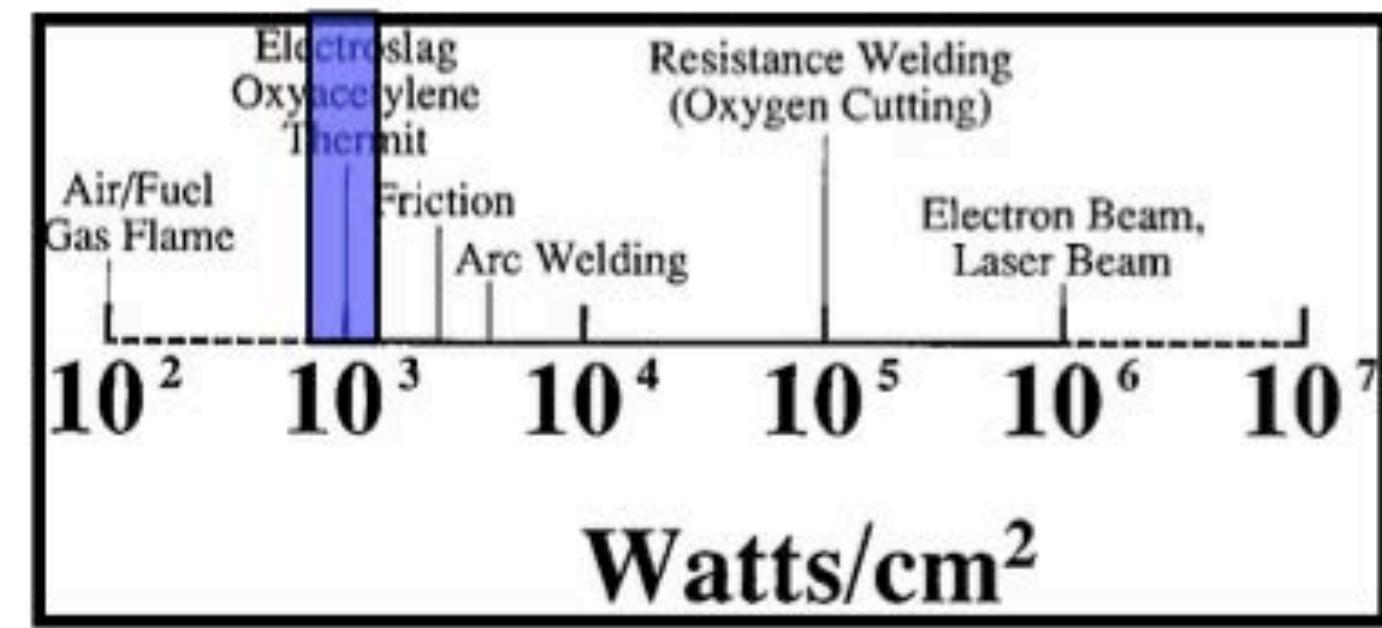
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Oxyfuel Gas Welding

air/fuel welding

low-cost and portable

oxidizing (high oxygen),
reducing (low oxygen), and
neutral flames



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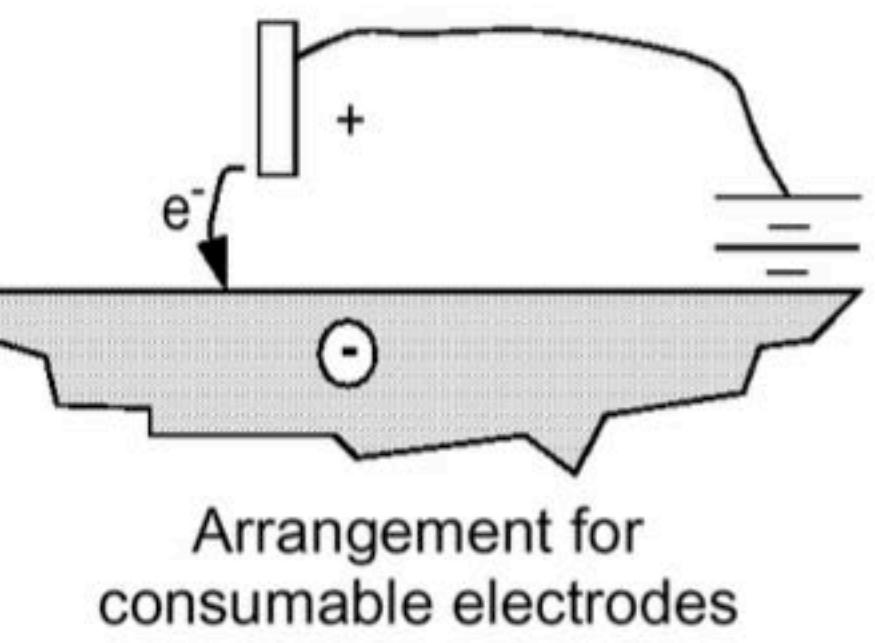
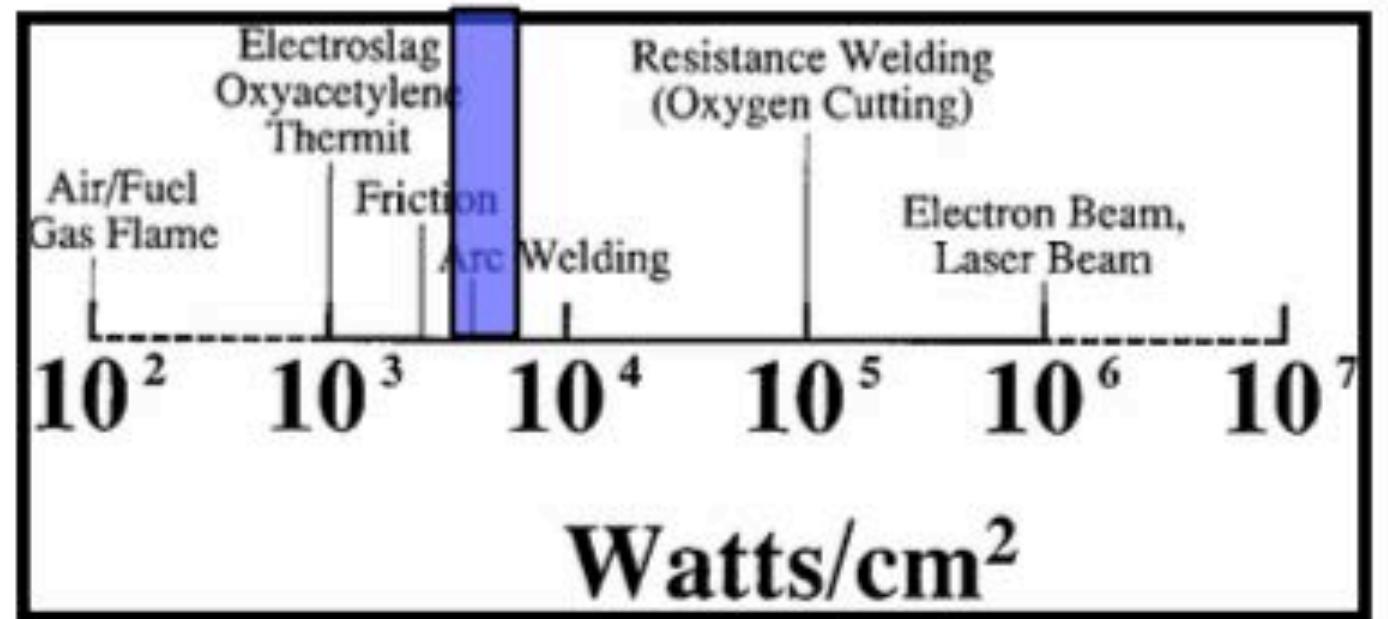
Arc Welding

voltage difference between electrode and workpiece

voltage ~100-500V

current ~50-300A

electrode may be consumed



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Processes and Types

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Arc Welding

filler metals

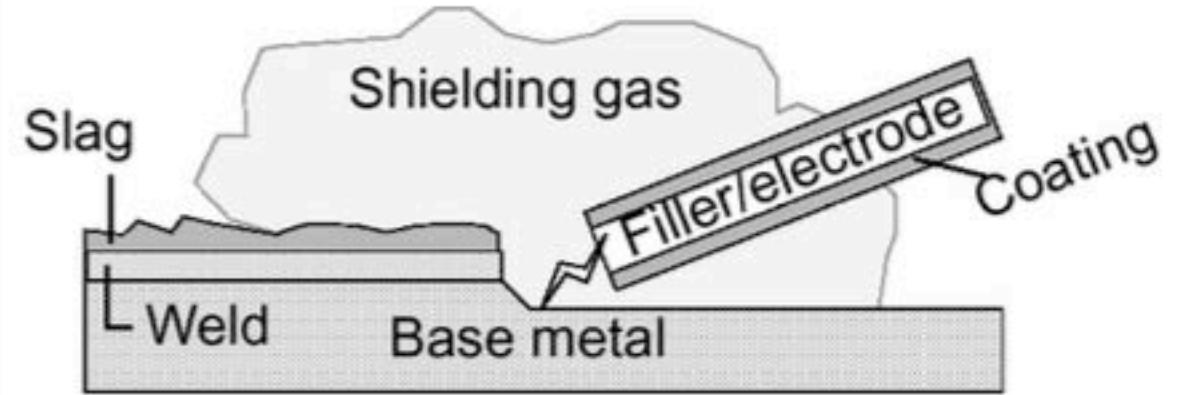
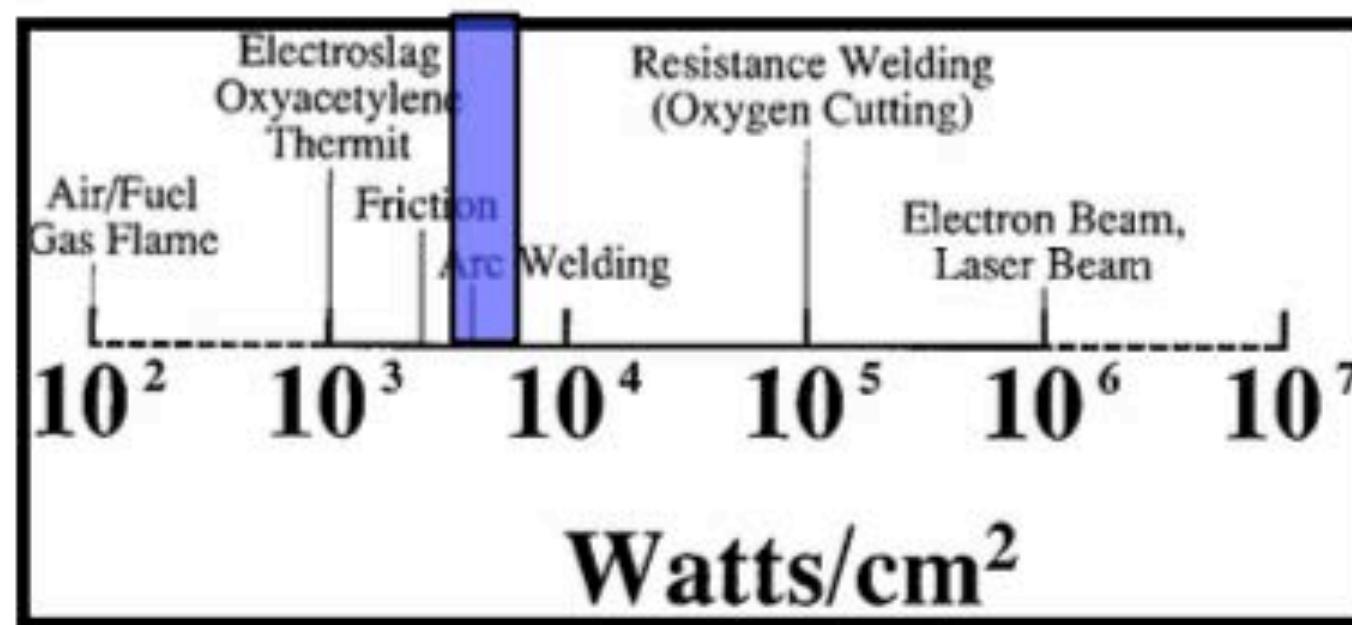
adds material to the weld zone

flux on/in filler prevents oxidation

slag protects molten puddle from oxidation

shielding

protects weld area contaminants



Joining II

Processes and Types

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Resistance Welding

high current: 3k-40k Amps

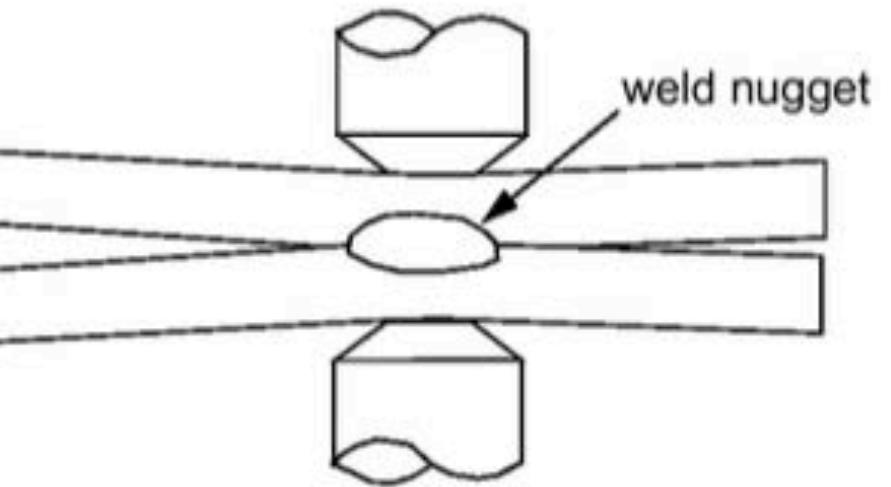
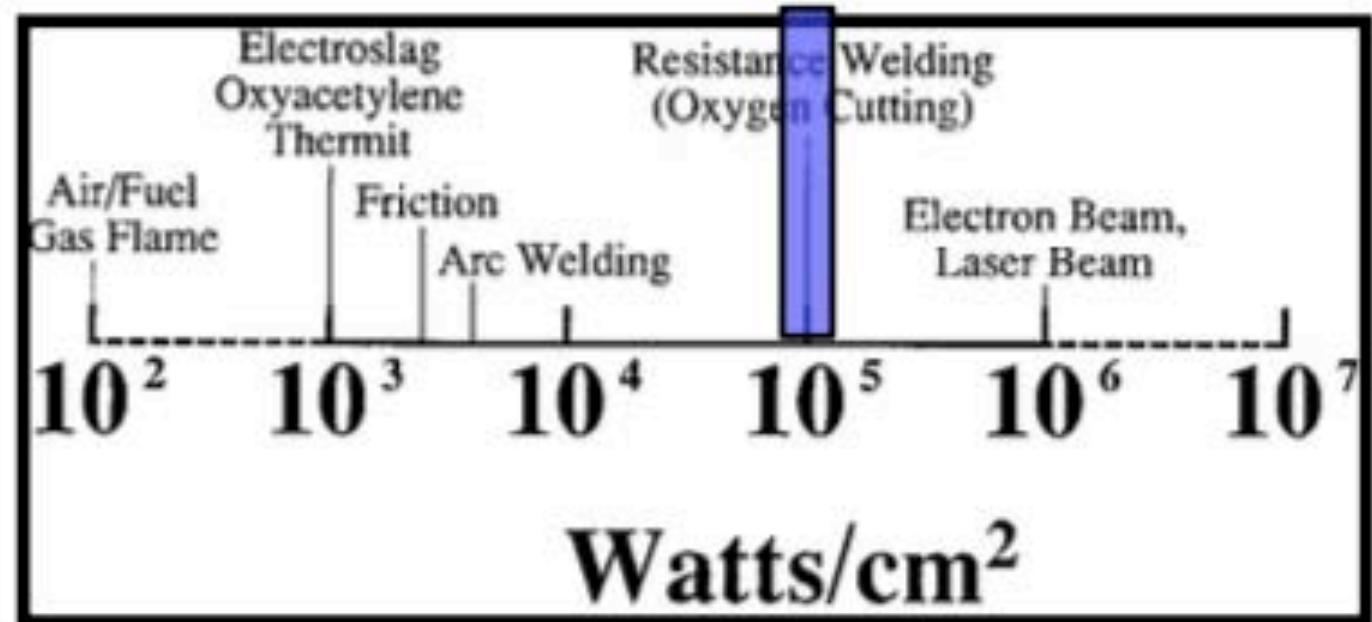
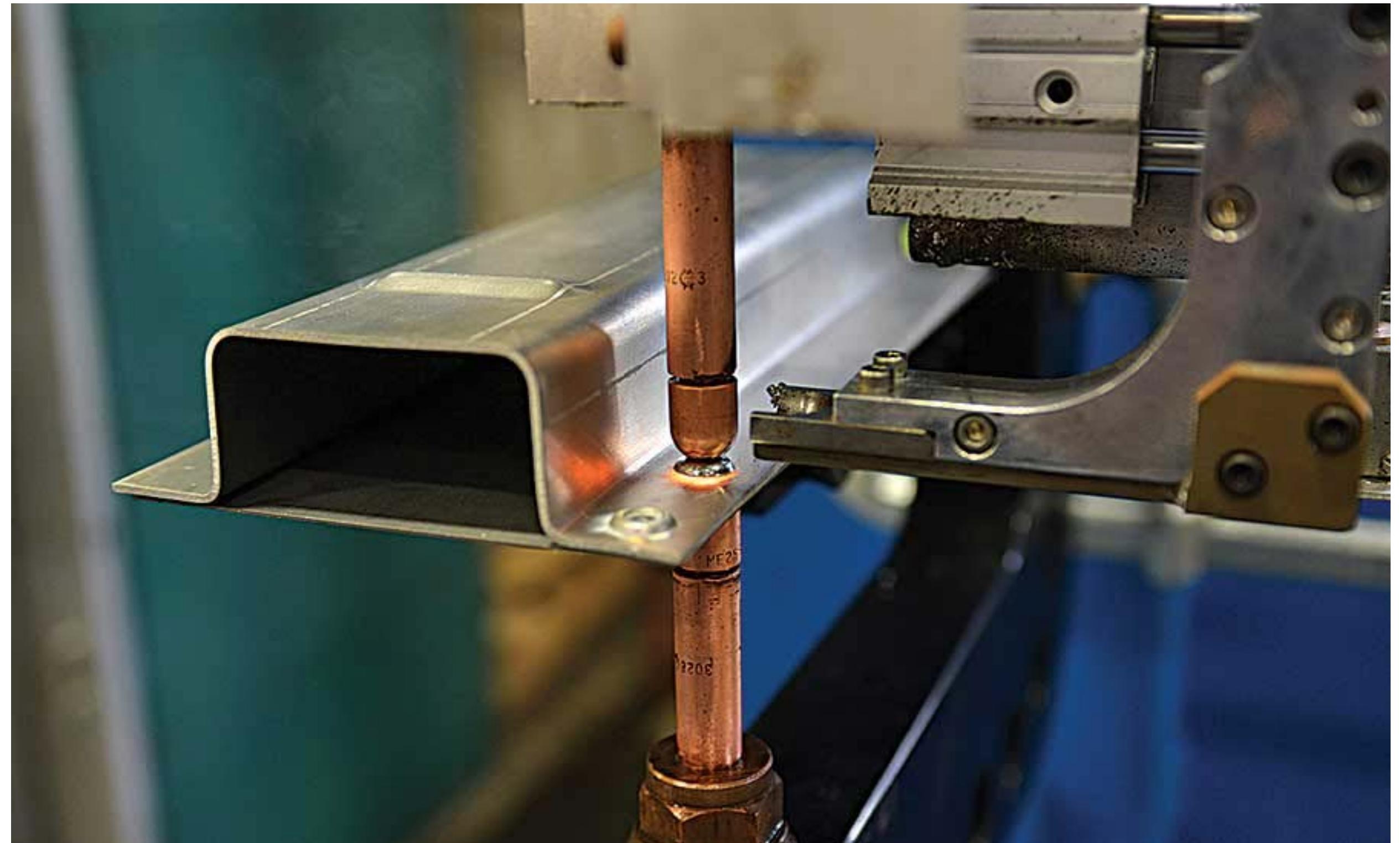
contact pressure + current + time

simple and reliable

welds difficult to inspect

energy: i^2Rt

melting in steel: $\sim 1400 \text{ J/g}$



Joining II

Processes and Types

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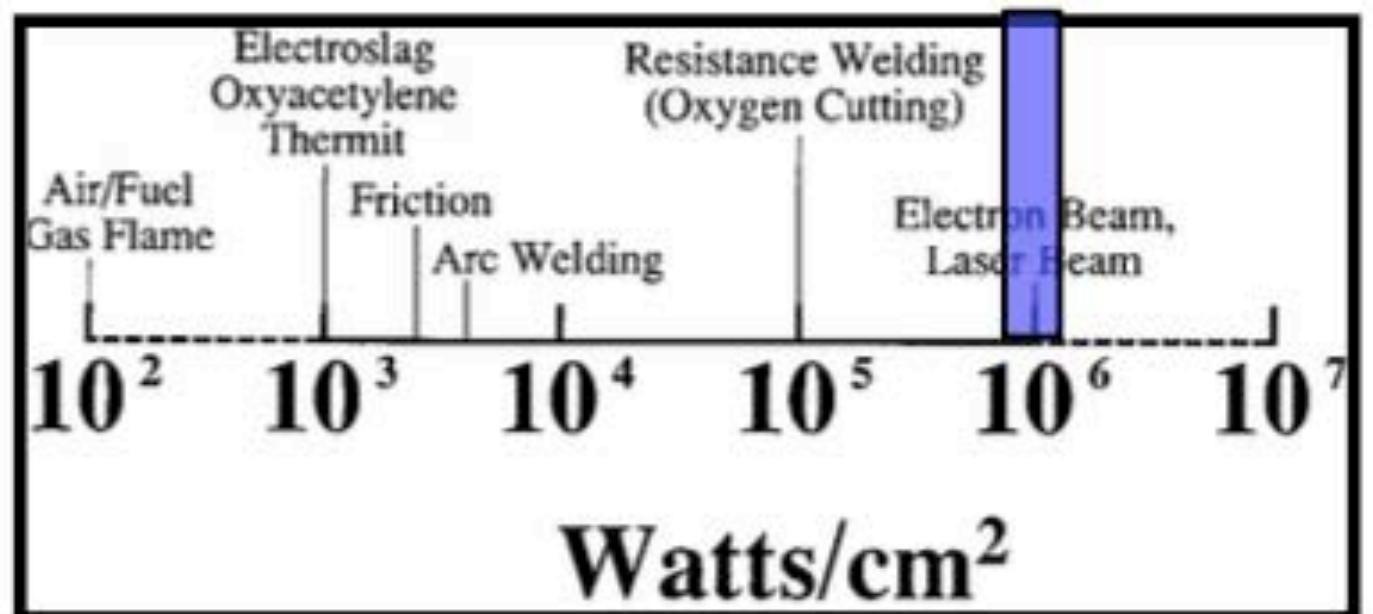
Fusion Welding

electron beam welding: electrons transfer energy

laser welding: photons transfer energy

small HAZ

expensive, careful fixturing needed



Joining II

Processes and Types

DF: Welding

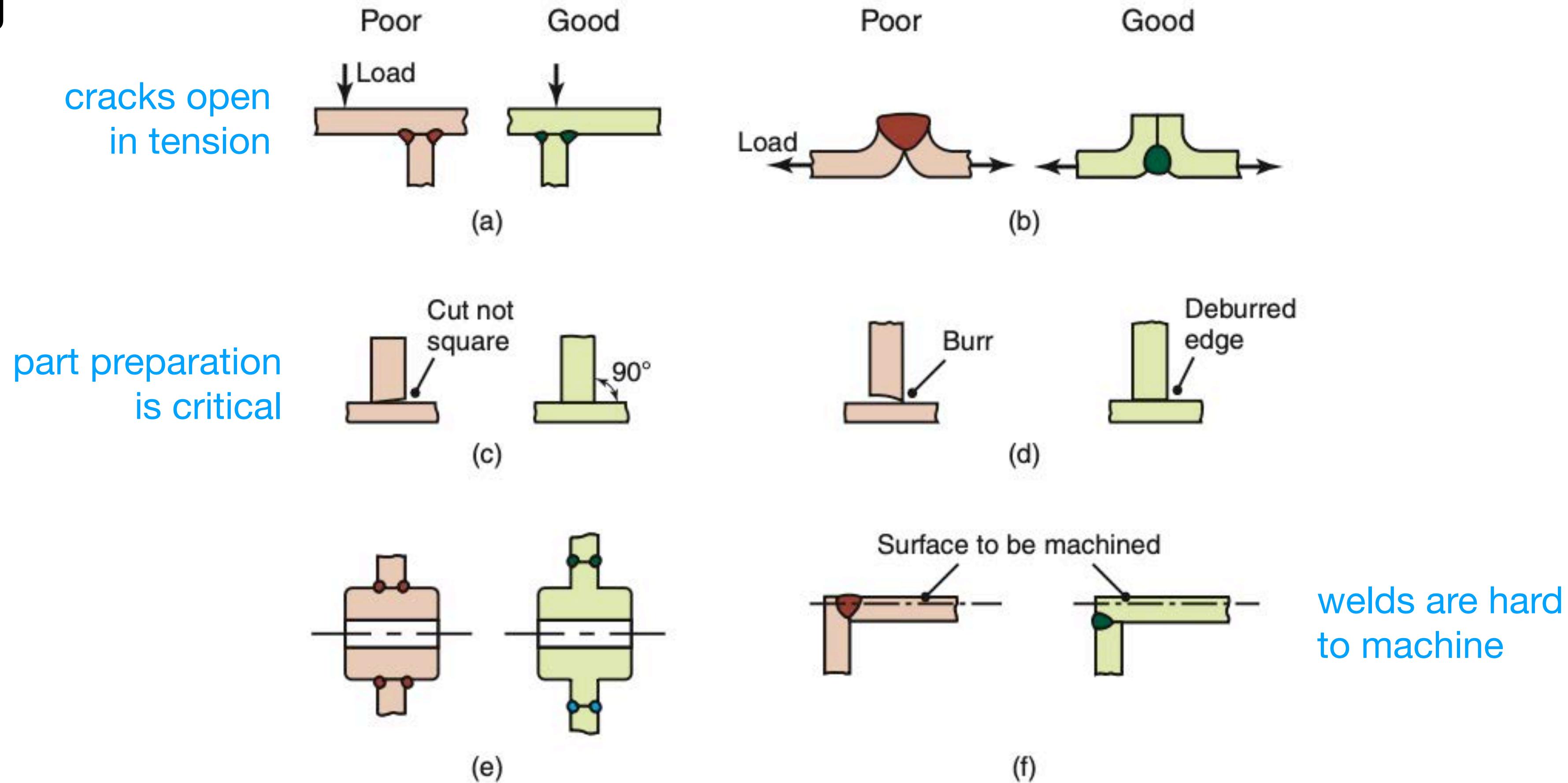


Figure 30.31: Some design guidelines for welds. Source: After J.G. Bralla.

Joining II

Processes and Types

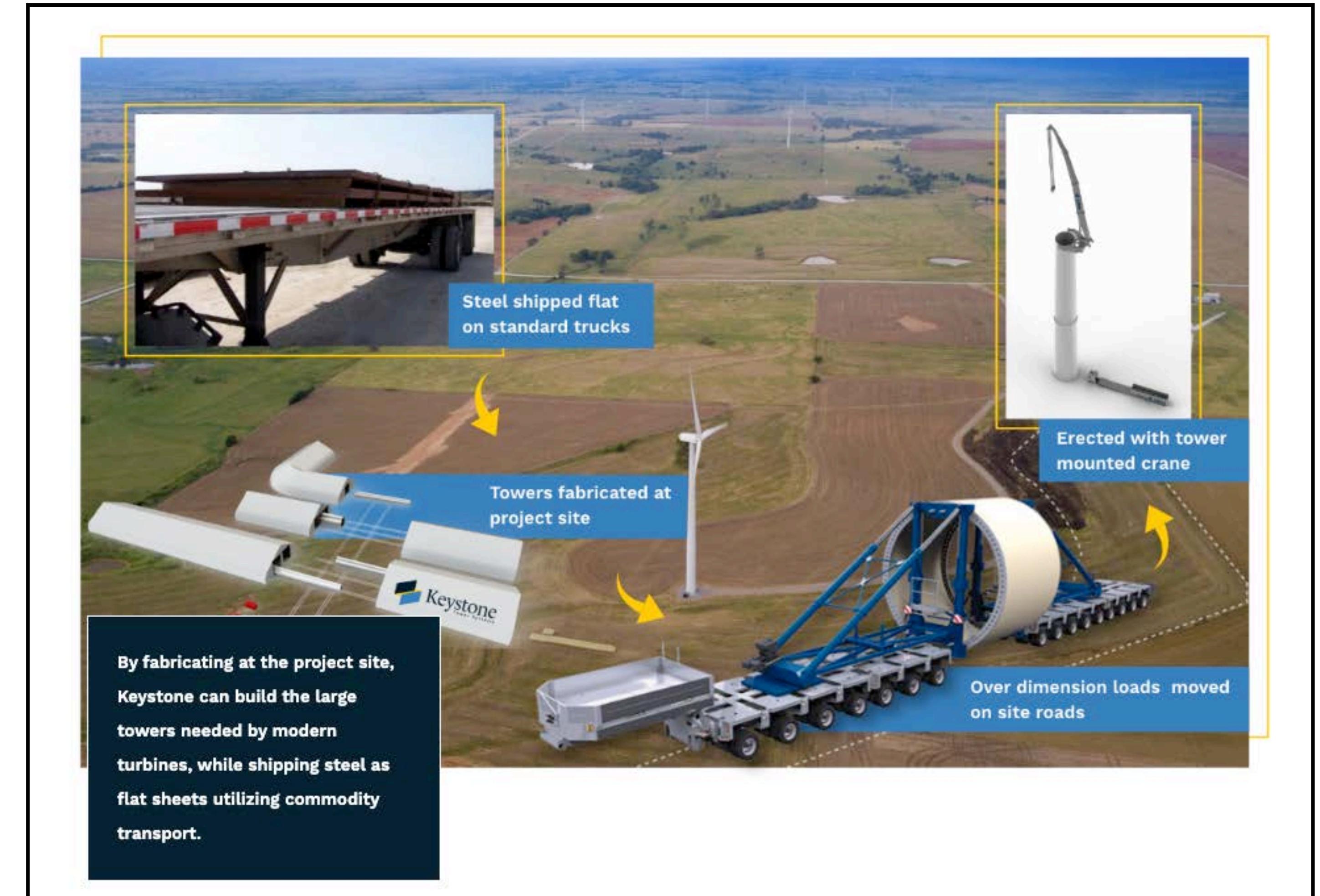
Sustainable Energy: Spiral Welding



Joining II

Processes and Types

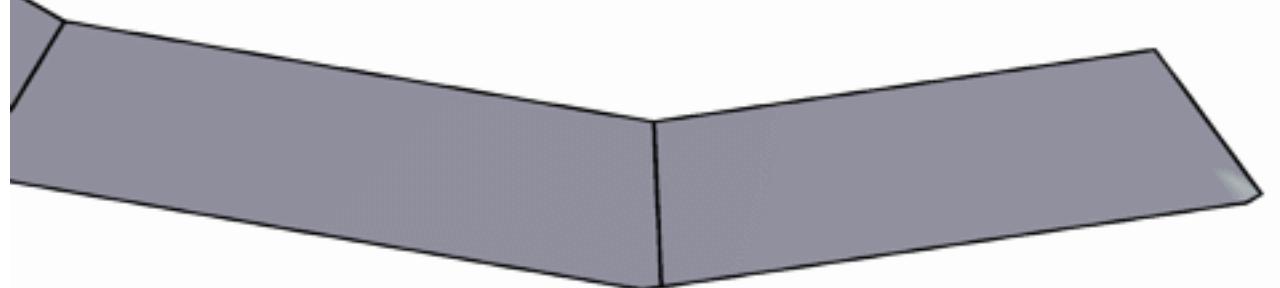
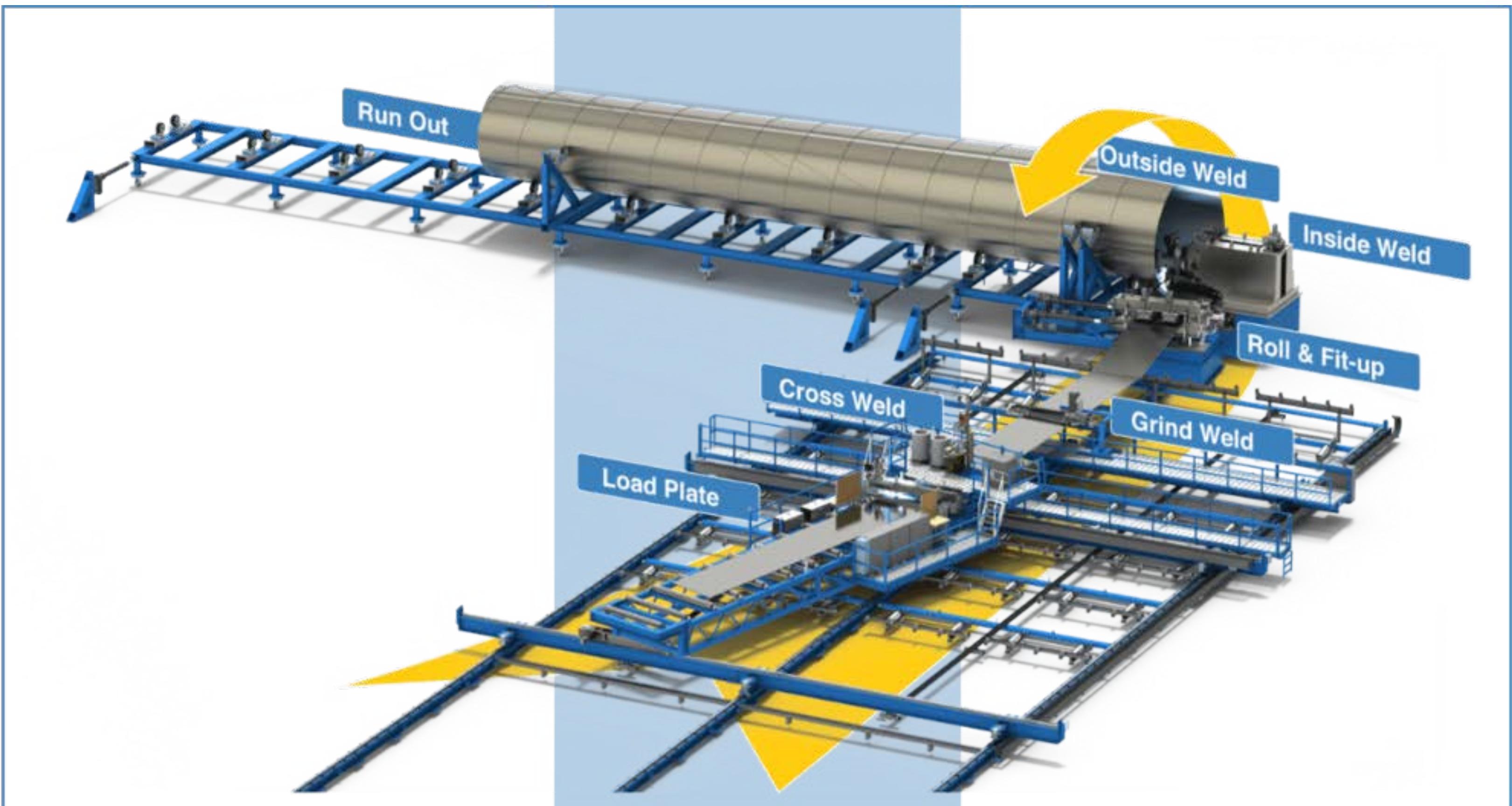
Sustainable Energy: Spiral Welding



Joining II

Processes and Types

Sustainable Energy: Spiral Welding





Joining II

Processes and Types

Sustainable Energy: Spiral Welding

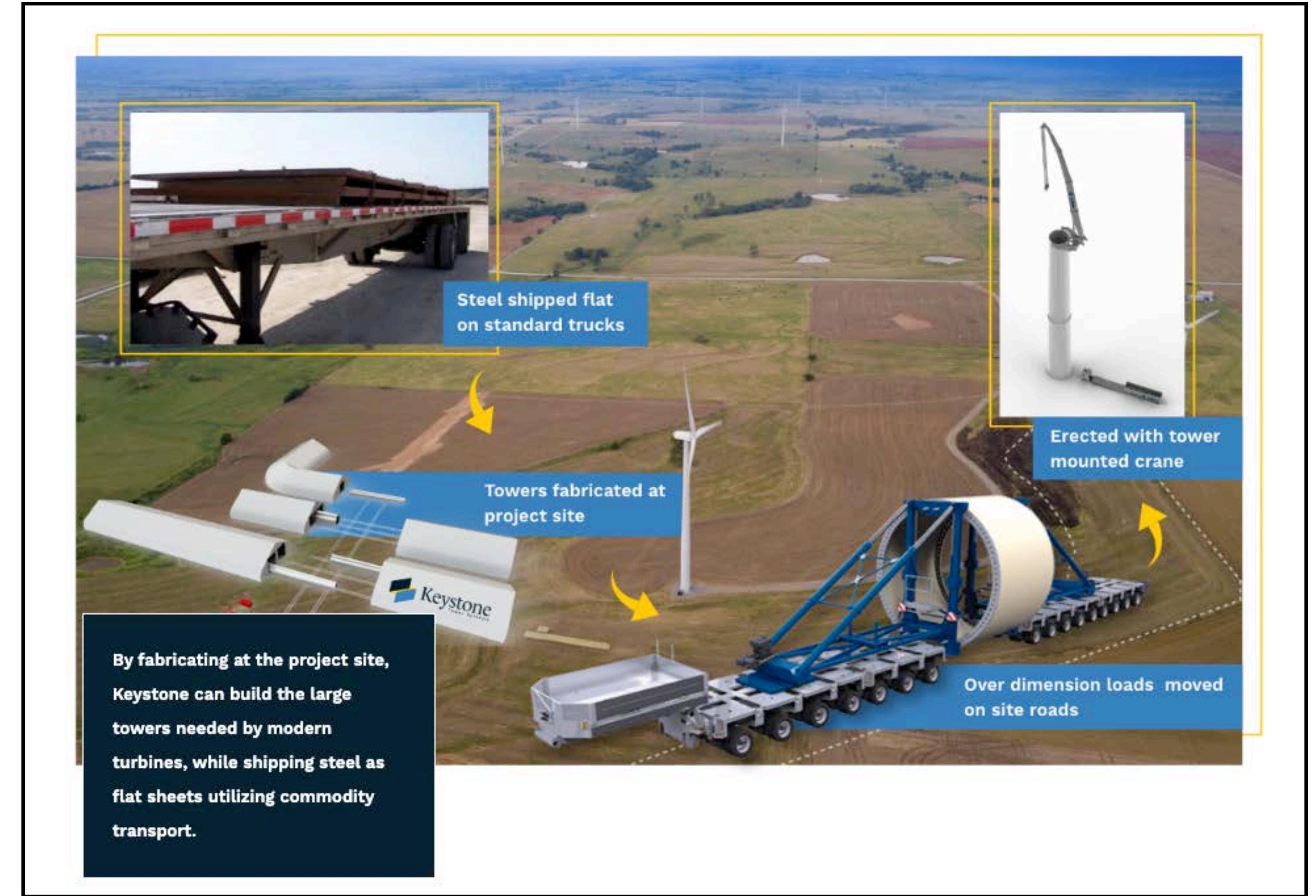


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